

GS64 GSM/GPRS Modem Integrators Manual

The information contained in this document is the proprietary information of Sony Ericsson Mobile Communications International. The contents are confidential and any disclosure to persons other than the officers, employees, agents or subcontractors of the owner or licensee of this document, without the prior written consent of **Sony Ericsson Mobile Communications International**, is strictly prohibited.

Further, no portion of this publication may be reproduced, stored in a retrieval system, or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, without the prior written consent of **Sony Ericsson Mobile Communications International**, the copyright holder.

First Edition (March 2006)

Sony Ericsson Mobile Communications International publishes this manual without making any warranty as to the content contained herein. Further **Sony Ericsson Mobile Communications International** reserves the right to make modifications, additions and deletions to this manual due to typographical errors, inaccurate information, or improvements to programs and/or equipment at any time and without notice. Such changes will, nevertheless be incorporated into new editions of this manual.

All rights reserved.

© **Sony Ericsson Mobile Communications International**, 2006

Publication number: LZT 123 1836

Printed in US

Contents

Overview	8
1 Introduction	9
1.1 TARGET USERS.....	9
1.2 PREREQUISITES	9
1.3 MANUAL STRUCTURE.....	9
1.4 NOTATION	10
1.5 ACKNOWLEDGEMENTS	10
2 GS64 WIRELESS MODEM.....	11
2.1 ABOUT THE GX64 FAMILY	11
2.2 WIRELESS MODEMS IN A COMMUNICATION SYSTEM.....	11
2.3 FEATURES	13
2.3.1 TYPES OF MOBILE STATION	13
2.3.2 SHORT MESSAGE SERVICE	14
2.3.3 VOICE CALLS	14
2.3.4 DATA	14
2.3.5 GPRS MULTI-SLOT SUPPORT.....	15
2.3.6 SIM CARD	15
2.3.7 POWER CONSUMPTION.....	15
2.3.8 OTHER FEATURES	16
2.4 SERVICE AND SUPPORT	16
2.4.1 WEB PAGES	16
2.4.2 AT COMMANDS MANUAL	16
2.4.3 M2MPOWER APPLICATION GUIDE	17
2.4.4 DEVELOPER'S KIT	17
2.5 PRECAUTIONS.....	17
2.6 GUIDELINES FOR SAFE AND EFFICIENT USE	17
2.6.1 GENERAL USAGE	18
2.6.2 RADIO FREQUENCY (RF) EXPOSURE AND SAR	18
2.6.3 PERSONAL MEDICAL DEVICES	19
2.6.4 DISPOSAL OF OLD ELECTRONIC EQUIPMENT	19

3	ABBREVIATIONS	20
	Integrating the Wireless Modem	22
4	Mechanical Description.....	23
4.1	INTERFACE DESCRIPTION	23
4.2	PHYSICAL DIMENSIONS	25
5	System Connector Interface	26
5.1	OVERVIEW	26
5.2	DEALING WITH UNUSED PINS.....	30
5.3	GENERAL ELECTRICAL AND LOGICAL CHARACTERISTICS.....	31
5.4	GROUNDS.....	32
5.4.1	ANALOGUE GROUND (AREF)	32
5.4.2	COMMON GROUND (GND).....	33
5.5	REGULATED POWER SUPPLY INPUT (VCC).....	34
5.6	VOLTAGE REFERENCE (VREF)	36
5.7	BATTERY CHARGING INPUT (CHG_IN)	37
5.7.1	CHARGING PROCESS	38
5.7.2	SERIES DIODE.....	39
5.7.3	BATTERY SELECTION.....	39
5.8	POWERING THE MODULE ON AND OFF (PON_L, PON_H)	43
5.8.1	VREF AS A POWER INDICATOR.....	43
5.8.2	MODULE ON & OFF SEQUENCE	44
5.8.2.1	POWER ON TIMING	45
5.8.3	TURNING THE MODULE OFF	46
5.9	ANALOGUE AUDIO	48
5.9.1	AUXILIARY AUDIO TO MOBILE STATION (AUXIP, AUXIN)	49
5.9.2	AUXILIARY AUDIO FROM MOBILE STATION (AUXOP, AUXON).....	49
5.9.3	MICROPHONE SIGNALS (MICIP, MICIN)	50
5.9.4	SPEAKER SIGNALS (EARP, EARN)	51
5.10	PCM DIGITAL AUDIO (SSP)	51
5.10.1	PCM DATA FORMAT	51
5.11	SERIAL DATA INTERFACES	53
5.11.1	UART1	53

5.11.2	SERIAL DATA SIGNALS (DTM1, DFM1).....	54
5.11.2.1	SERIAL DATA FROM WIRELESS MODEM (DFM1)	54
5.11.2.2	SERIAL DATA TO WIRELESS MODEM (DTM1)	54
5.11.3	CONTROL SIGNALS (RTS1, CTS1, DTR1, DSR1, DCD1, RI).....	55
5.11.3.1	HARDWARE FLOW CONTROL RTS1 AND CTS1	55
5.11.3.2	REQUEST TO SEND (RTS1).....	55
5.11.3.3	CLEAR TO SEND (CTS1)	55
5.11.3.4	DATA TERMINAL READY (DTR1).....	55
5.11.3.5	DATA SET READY (DSR1)	56
5.11.3.6	DATA CARRIER DETECT (DCD1)	56
5.11.3.7	RING INDICATOR (RI).....	56
5.11.4	UART2 (DTM2, DFM2).....	57
5.11.4.1	TRANSMITTED DATA (DTM2).....	57
5.11.4.2	RECEIVED DATA (DFM2).....	57
5.11.4.3	REQUEST TO SEND (RTS2).....	57
5.11.4.4	CLEAR TO SEND (CTS2)	57
5.11.5	USB	58
5.11.6	SIM CARD INTERFACE	59
5.11.7	SIM DETECTION (SIMDET).....	60
5.12	SYNCHRONOUS SERIAL PORT (SSP) INTERFACE [TO BE IMPLEMENTED IN A FUTURE RELEASE]	60
5.13	MEMORY CARD INTERFACE (SD/MMC) [TO BE IMPLEMENTED IN A FUTURE RELEASE].....	61
5.13.1	MULTIMEDIA CARD SYSTEM	61
5.13.2	SECURE DIGITAL MEMORY CARD SYSTEM	62
5.14	SERVICE/PROGRAMMING	63
5.15	LED [TO BE IMPLEMENTED IN A FUTURE RELEASE]	63
5.16	GENERAL PURPOSE IO.....	65
5.16.1	EMBEDDED APPLICATIONS	66
5.17	KEYBOARD SIGNALS (KEYROW, KEYCOL)	67
5.18	ANALOGUE TO DIGITAL CONVERTERS (ADIN1, ADIN2, ADIN3, ADIN4).....	67
5.19	BURST TRANSMISSION (TX_ON).....	69
5.20	REAL TIME CLOCK	69
5.20.1	REAL TIME CLOCK BACKUP SUPPLY (VRTC)	70
5.20.2	RTC ALARM (ALARM)	71
5.20.2.1	ALARM OUTPUT FROM THE MODULE	71
5.20.3	ALARM UTILIZATION AS A WAKE-UP.....	72
5.21	RINGER OUTPUT (BUZZER) [TO BE IMPLEMENTED IN A FUTURE RELEASE]	73
6	Antenna Connector	74

7	Hints for Integrating the Wireless Modem.....	75
7.1	SAFETY ADVICE AND PRECAUTIONS	75
7.1.1	GENERAL	75
7.2	SIM CARD	76
7.3	ANTENNA	76
7.4	INSTALLATION OF THE WIRELESS MODEM.....	77
7.4.1	WHERE TO INSTALL THE WIRELESS MODEM.....	77
7.4.1.1	ENVIRONMENTAL CONDITIONS.....	77
7.4.1.2	SIGNAL STRENGTH	77
7.4.1.3	CONNECTION OF COMPONENTS TO WIRELESS MODEM.....	78
7.4.1.4	NETWORK AND SUBSCRIPTION.....	78
7.4.2	HOW TO INSTALL THE WIRELESS MODEM.....	79
7.4.2.1	POWER SUPPLY	79
7.4.2.2	GROUNDS	79
7.4.2.3	AUDIO.....	79
7.4.2.4	SOFTWARE UPGRADE.....	79
7.5	ANTENNA	80
7.5.1	GENERAL	80
7.5.2	ANTENNA TYPE.....	80
7.5.3	ANTENNA PLACEMENT	81
7.5.4	THE ANTENNA CABLE.....	81
7.5.5	POSSIBLE COMMUNICATION DISTURBANCES	81
8	Embedded Applications	83
8.1	FEATURES	83
8.2	IMPLEMENTATION.....	83
8.2.1	LIMITATIONS	83
8.2.2	M2MPOWER IDE (INTEGRATED DEVELOPMENT ENVIRONMENT).....	84
9	TCP/IP Stack.....	85
9.1	IMPLEMENTATION.....	85
10	Technical Data.....	86
10.1	MECHANICAL SPECIFICATIONS.....	86
10.2	POWER SUPPLY VOLTAGE, NORMAL OPERATION.....	87
10.3	RADIO SPECIFICATIONS	87

10.4	SIM CARD.....	87
10.5	ENVIRONMENTAL SPECIFICATION	88
11	Regulatory Notices	90
12	Introduction to the Universal Developer's Kit.....	92

Overview

1 Introduction

1.1 Target Users

The GS64 wireless modems are designed to be integrated into machine-to-machine or man-to-machine communications applications.

They are intended to be used by manufacturers, system integrators, applications developers and developers of wireless communications equipment.

1.2 Prerequisites

It is assumed that the person integrating the wireless modem into an application has a basic understanding of the following:

- GSM networking;
- Wireless communication and antennas (aerials)
- AT commands
- ITU-T standard V.24/V.28
- Micro controllers and programming
- Electronic hardware design

1.3 Manual Structure

The manual is composed of three parts:

Part 1 – Overview

This section provides a broad overview of the Gx64 family and includes a list of abbreviations used in the manual.

Part 2 – Integrating the Wireless modem

This section describes each of the signals available on the GS64 wireless modem, along with mechanical information. The section also provides you with design guidelines and what is needed to commercialize an application from a regulatory point of view.

Part 3 – Developer’s Kit

This section lists the contents of the Developer’s Kit and provides the information to setup and use the equipment.

1.4 Notation

The following symbols and admonition notation are used to draw the readers attention to notable, or crucially–important information.



Note

Draws the readers attention to pertinent, useful or interesting information



Tip

Provides advice, suggestions, guidance or recommendations which augment the formal text



Caution

Cautionary information must be heeded, it draws the readers attention to the need for understanding, care or watchfulness in relation to the information provided



Warning

Notes marked warning must be heeded, they alert readers to precautionary measures, risks, hazards or safety information which directly effects equipment function, warranty or personnel safety



Danger

This information must be heeded, it identifies information and cautionary behavior that otherwise ignored could result in catastrophic equipment failure, bodily injury or death

1.5 Acknowledgements

Parts of this document, including text passages, tables and illustrations, are reproduced from copyright information by kind permission of Agere Systems Inc.

2 GS64 WIRELESS MODEM

2.1 About the Gx64 Family

The Sony Ericsson Gx64 family of devices are Quad Band GSM/GPRS wireless modems operating in the GSM 850/900/1800/1900 bands.

The products belong to a new generation of Sony Ericsson wireless modems, and are intended to be used in machine-to-machine applications and man-to-machine applications. They are used when there is a need to send and receive data (by SMS, CSD, or GPRS), and make voice calls over the GSM network.

Two software variants of the Gx64 devices exist. One variant is designed to be controlled from a micro-controller situated on the host application. The other variant offers the option to run applications embedded onto the module itself. When using the embedded application version the controlling script can be run internal to the module, with or without the use of an external control.

A typical application, involves a micro-controller and a wireless modem, in which the micro-controller sends AT commands to the wireless modem via an RS232 communications link.

2.2 Wireless modems in a Communication System

Figure 2.2-1 and *Figure 2.2-2* illustrate the main blocks of a wireless communication system using the wireless modem. *Figure 2.2-1* shows the communication system when the script is embedded on the wireless modem and *Figure 2.2-2* shows the communication system when a micro-controller is used. They also show the communication principles of the system and the interface between the wireless modem and the application. The definitions in the figures, as used elsewhere in this manual, are in accordance with the recommendations of 3GPP TS 27.007.

- The MS (mobile station) represents the wireless modem and SIM card. The wireless modem excluding SIM card, is known as the ME (mobile equipment).
- The DTE (data terminal equipment) is the controlling application. This can be either an external host or an internal embedded application
- The DCE (data circuit terminating equipment) is the serial communication interface of the MS.

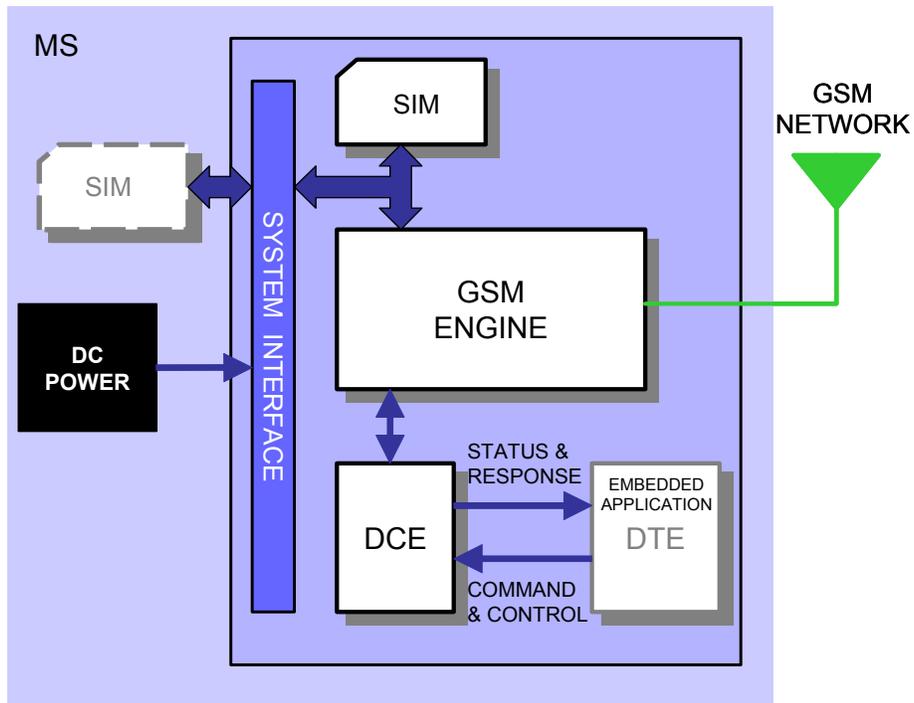


Figure 2.2-1 Main Blocks in a Wireless System (embedded application)

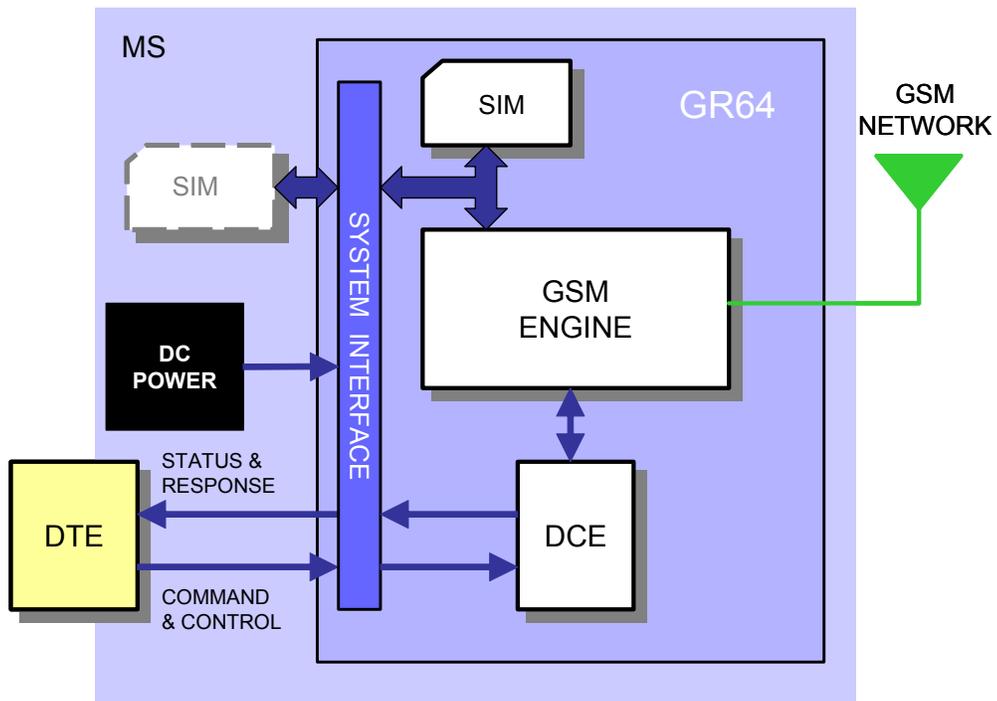


Figure 2.2-2 Main Blocks in a Wireless System (external micro-controller)

In accordance with the recommendations of ITU-T (International Telecommunication Union – Telecommunications Standardization Sector) V.24, the TE communicates with the MS over a serial interface.

The functions of the wireless modem follow the recommendations provided by 3GPP (3rd Generation Partnership Project) and ITU-T. 3GPP is a collaboration agreement that was established in December 1998. The collaboration agreement brings together a number of telecommunications standards bodies which are known as *Organizational Partners*. The current Organizational Partners are ARIB, CCSA, ETSI, ATIS, TTA, and TTC.

3GPP specifies a set of AT commands for controlling the GSM element of the wireless modem; these commands are supplemented by Sony Ericsson specific commands.

To find out how to work with AT commands, see the AT Commands Manual.

2.3 Features

The wireless modem performs a set of telecom services (TS) according to 3GPP release 99 and ITU-T. The functions of the wireless modem are implemented by issuing AT commands over a serial interface.

2.3.1 Types of Mobile Station

The GS64 is a fully Quad Band capable GSM/GPRS mobile station with the characteristics shown in the table below.

Feature		GSM850	E-GSM900	GSM1800	GSM1900
Frequency range (MHz)	Tx	824–849	880–915	1710–1785	1850–1910
	Rx	869–894	925–960	1805–1880	1930–1990
Channel spacing		200kHz	200kHz	200kHz	200kHz
Number of channels		124	174	374	299
Number of Time Division slots		8	8	8	8
Duplex spacing		45MHz	45MHz	95MHz	80MHz
GSM power class		4 (2W)	4 (2W)	1 (1W)	1 (1W)
Modulation		GMSK			
Receive sensitivity		<–102dBm at antenna connector			
GPRS multi-slot class		Class 10			

2.3.2 Short Message Service

The wireless modem supports the following SMS services:

- Sending; MO (mobile-originated) with both PDU (protocol data unit) and text mode supported
- Receiving; MT (mobile-terminated) with both PDU and text mode supported
- CBM (cell broadcast message); a service in which a message is sent to all subscribers located in one or more specific cells in the GSM network (for example, traffic reports)
- SMS status report according to 3GPP TS 23.40

The maximum length of a text mode SMS message is 160 characters using 7-bit encoding. The wireless modem supports up to six concatenated messages to extend this function. Concatenation is performed by the host application.

2.3.3 Voice Calls

The wireless modem offers the capability of MO (mobile originated) and MT (mobile terminated) voice calls, as well as supporting emergency calls. Multi-party, call waiting and call divert features are available. Some of these features are network-operator specific.

For the inter-connection of audio, the wireless modem offers both single ended and balanced analogue input and output lines. Direct interface to the digital PCM (pulse code modulation) bus used within the wireless modem is available, thus by-passing the internal analogue circuitry. The wireless modems support HR, FR, EFR and AMR vocoders.

2.3.4 Data

The wireless modem supports the following data protocols:

- GPRS (General Packet Radio Service)

The wireless modem is a Class B terminal. The wireless modem is GPRS multislot class10 enabled, capable of receiving at a maximum of four timeslots per frame (down link), and transmitting in two timeslots per frame (up link). See section 2.3.5 for multi-slot allocation by class.

- CSD (Circuit Switched Data)

The GS64 wireless modem is capable of establishing a CSD communication at 9.6 kbps over the air.

2.3.5 GPRS Multi-Slot Support

GSM Multi-slot classes supported by Gx64 devices

Multislot Class	Maximum slot allocation			Allowable Configuration	Max data rate
	Downlink	Uplink	Active		
8	4	1	5	1 up; 4 down	8–12Kbps Send 32–48Kbps Receive
10	4	2	5	1 up; 4 down	8–12Kbps Send 32–48Kbps Receive
				2 up; 3 down	16–24Kbps Send 24–36Kbps Receive

2.3.6 SIM Card

The GS64 supports an external SIM card through its system connector. Both 3V and 1.8V SIM technology is supported. Older, 5V SIM technology is not supported.

A mechanical variant of the GS64 also supports an on-card SIM. For dual SIM support, automated SIM-switching is available. Only one SIM is active at any one time, it is not possible to concurrently register on more than one network.

2.3.7 Power Consumption

Feature		Sleep Mode DRX 8	Idle Mode	Transmit Operation
GSM850 & E-GSM900	Voice/CSD	1.6 mA	17 mA	2000 mA
	Data (GPRS)			
GSM1800 & GSM1900	Voice/CSD	1.6 mA	16 mA	1450 mA
	Data (GPRS)			

The power consumption figures shown represent average current for maximum transmitted power, single uplink (transmit) slot, single downlink (receive) slot. The module will consume more average power in different multi-slot configurations, the worst case being that of two uplink and three downlink slots.

2.3.8 Other Features

The GS64 supports many other features, including :

- multiplexing in accordance with 3GPP TS 27.010
- GPS interoperability
- SIM application tool kit, class 2 release 99 compliant
- On board TCP/IP stack

In addition, customers have the option of a GS64 software variant which adds embedded application functionality.

2.4 Service and Support

2.4.1 Web Pages

Visit the Sony Ericsson M2M extranet web site for the following information:

- where to buy wireless modems or for recommendations concerning accessories and components
- local contact details for customer support in your region
- FAQs (frequently asked questions)
- documentation related to integrating the module, including application notes, design guides and AT command manuals

Access to the Sony Ericsson extranet site requires a user account and password. Accounts can be arranged through your local account manager.

The extranet web site address is:

<https://extranet.sonyericsson.com/collaborationarea/m2m/default.aspx>

2.4.2AT Commands Manual

The AT Commands Manual provides users with all the AT commands that can be used with the wireless modem. AT commands appear in logical groups and contain the command, a description of its functionality and an example of use.

2.4.3 M2mpower Application Guide

The M2mpower Application Guide provides users with all the information they need to build an application using the M2mpower support environment. This manual is supplied as part of the M2mpower package.

2.4.4 Developer's Kit

Sony Ericsson provides the developer's kit to get you started quickly. The kit includes the necessary hardware required to begin the development of an application. It includes the following:

- This Integrator's Manual
- Developer's kit hardware
- Developer's kit accessories
- Power supply
- RS232 cable
- Headset
- Antenna

User need to order the M2M module(s) of their choice, and provide a computer or micro-controller. The AT command manual provides the necessary command and control reference to drive the module.

2.5 Precautions

The wireless modems are ESD protected up to $\pm 2\text{kV}$ on all pins other than the SIM interface. The SIM interface is protected up to $\pm 15\text{kV}$. Integrators must follow electronic device handling precautions when working with any electronic device system to ensure no damage occurs to the host or the wireless modem. In the section 'Integrating the Wireless modem', users will find more information about safety and product care. Do not exceed the environmental and electrical limits as specified in 'Technical Data' section.

2.6 Guidelines for Safe and Efficient Use

Users must follow the general usage outlined in this chapter before using the GS64 for any purpose.

2.6.1 General Usage

- Always treat the product with care and keep it in a clean and dust-free place
- Do not expose the product to liquid
- Avoid exposing the product to moisture or high humidity environments
- Do not expose the product to extreme high or low temperatures beyond those specified for operation and storage
- Do not expose the product to open flames or lit tobacco products
- Do not drop, throw or try to bend the product
- Do not paint the product
- Do not use the product near medical equipment without requesting permission
- Do not use the product when in, or around aircraft, or areas posted “turn off two-way radio”
- Do not use the product in an area where a potentially explosive atmosphere exists
- Do not place the product or install wireless equipment in the area above a vehicle’s air bag
- Do not attempt to disassemble the product; only Sony Ericsson authorized personnel should perform servicing

2.6.2 Radio Frequency (RF) exposure and SAR

Your wireless modem device is a low-power radio transmitter and receiver (transceiver). When it is turned on, it emits low levels of radio frequency energy (also known as radio waves or radio frequency fields).

Governments around the world have adopted comprehensive international safety guidelines, developed by scientific organizations, e.g. ICNIRP (International Commission on Non-Ionizing Radiation Protection) and IEEE (The Institute of Electrical and Electronics Engineers Inc.), through periodic and thorough evaluation of scientific studies. These guidelines establish permitted levels of radio wave exposure for the general population. The levels include a safety margin designed to assure the safety of all persons, regardless of age and health, and to account for any variations in measurements.

Specific Absorption Rate (SAR) is the unit of measurement for the amount of radio frequency energy absorbed by the body when using a transceiver. The SAR value is determined at the highest certified power level in laboratory conditions, but the actual SAR level of the transceiver while operating can be well below this value. This is because the transceiver is designed to use the minimum power required to reach the network.

The GS64 wireless modem device has been approved for applications where the antenna is located >20cm from the body. In all other configurations the integrator is responsible for meeting the local SAR regulations.

Integrators of the GS64 wireless modem device are responsible for ensuring that they meet the SAR regulatory requirements of the countries in which they intend to operate the device, and that their documentation contains the relevant SAR declaration, certification information, and user guidance as appropriate.

More information on radio frequency exposure and SAR can be found at www.sonyericsson.com.

2.6.3 Personal Medical Devices

Wireless modem devices may affect the operation of cardiac pacemakers, hearing aids and certain other implanted equipment. If a minimum distance of 15 cm (6 inches) is maintained between the GS64 module's radiating antenna and a pacemaker, the risk of interference is limited. If the integrator's application is likely to be situated in the vicinity of personnel, a suitable warning should be contained in the equipment manual to this effect.

2.6.4 Disposal of Old Electronic Equipment



This symbol on the product or on its packaging indicates that this product shall not be treated as household waste. Instead it shall be handed over to an appropriate collection point for the recycling of electrical and electronic equipment. By ensuring this product is disposed of correctly, you will help prevent potential negative consequences for the environment and human health, which could otherwise be caused by inappropriate waste handling of this product. The recycling of materials will help to conserve natural resources. For more detailed information about recycling of this product, please contact your local city office, your household waste disposal service or the Sony Ericsson regional sales office.

3 ABBREVIATIONS

Abbreviation	Explanation
ADC	Analogue to Digital Converter
AMR	Adaptive Multi Rate
ATMS	Audio to Mobile Station
AFMS	Audio from Mobile Station
CBM	Cell Broadcast Message
CBS	Cell Broadcast Service
CSD	Circuit Switched Data
DCE	Data Circuit Terminating Equipment
DK	Developer's Kit
DTE	Data Terminal Equipment
DTMF	Dual Tone Multi Frequency
EA	Embedded Application
EFR	Enhanced Full Rate
EMC	Electro-Magnetic Compatibility
ETSI	European Telecommunication Standards Institute
FR	Full Rate
GPRS	General Packet Radio Service
GPS	Global Positioning System
GSM	Global System for Mobile Communication
HR	Half Rate
IDE	Integrated Development Environment
IP	Internet Protocol
ITU-T	International Telecommunication Union - Telecommunications (Standardisation Sector)
LDO	Low Drop Out (voltage regulator)
M2mpower	Sony Ericsson's powerful support environment
ME	Mobile Equipment
MMCX	Micro Miniature Coax
MO	Mobile Originated
MS	Mobile Station
MT	Mobile Terminated
PCM	Pulse Code Modulation

Abbreviation	Explanation
PDU	Protocol Data Unit
RF	Radio Frequency
RFU	Reserved for Future Use
RLP	Radio Link Protocol
RTC	Real Time Clock
SDP	Service Discovery Protocol
SIM	Subscriber Identity Module
SMS	Short Message Service
TCP	Transport Control Protocol
UDP	User Datagram Protocol

Integrating the Wireless Modem

4 Mechanical Description

4.1 Interface Description

The pictures below show the mechanical design of the wireless modem along with the positions of the different connectors and mounting holes. The wireless modem is protected with tin coated steel ASI 1008/1010 covers that meet the environmental and EMC requirements.

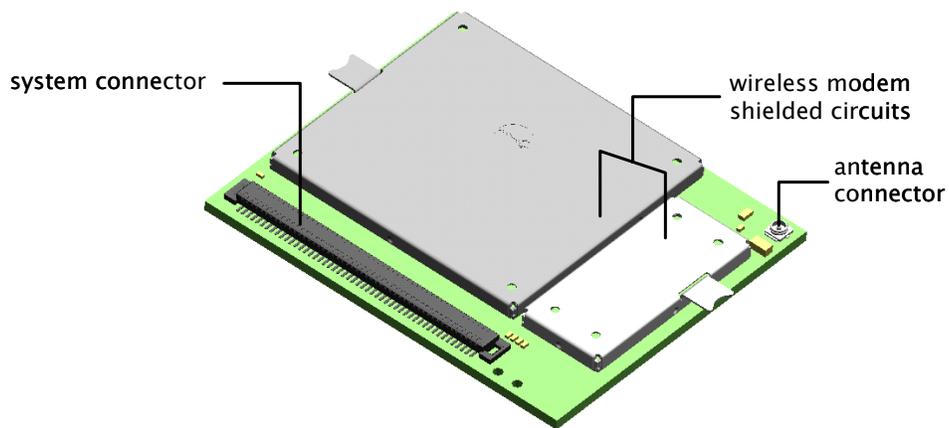


Figure 4.1-1 Wireless modem viewed from below

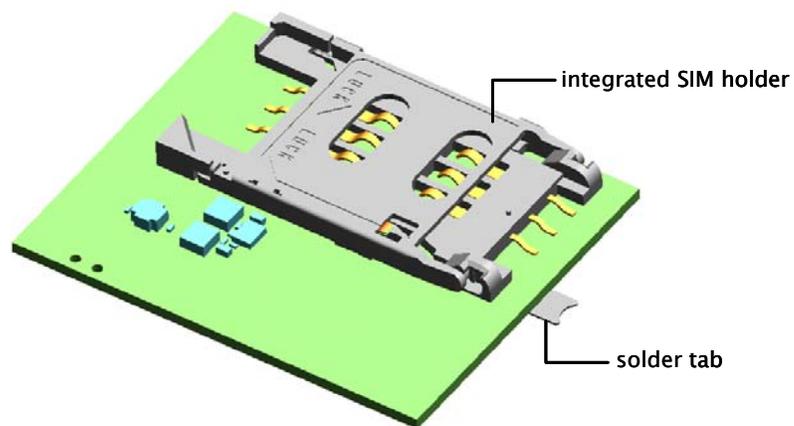


Figure 4.1-2 Wireless modem, viewed from above (Integrated SIM holder version)

Please note the following:

- Keypad, display, microphone, speaker and battery are not part of the wireless modem
- For the GS64 variant without an integrated SIM holder, the SIM card is mounted in the user application, external to the wireless modem (this is also an option for the integrated SIM holder variant)
- The GS64 variant without an integrated SIM holder has no components mounted on the top-side
- The System Connector is a 100-pin, narrow (0.5 mm) pitch type designed for board-to-board mating. The pins and their electrical characteristics are described in Section 5, together with the System Connector Interface.
- Information about the Antenna Connector is found in Section 6.
- Antenna Connector details are found in Section 6.

4.2 Physical Dimensions

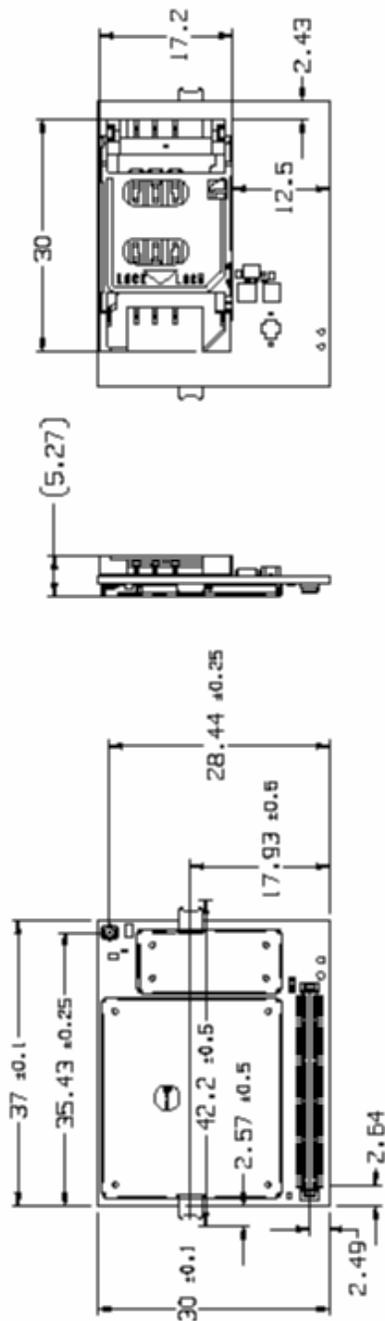


Figure 4.2-1 Dimensions of the Wireless modem (Integrated SIM variant)
Measurements are given in millimeters. See also Technical Data, in Section 10 .

5 System Connector Interface

5.1 Overview

Electrical connections to the wireless modem (except the antenna), are made through the System Connector Interface. The system connector is a 100-pin, narrow (0.5 mm) pitch device designed for board-to-board connectivity.

Figure 5.1-1 below shows the numbering of the connector pins.

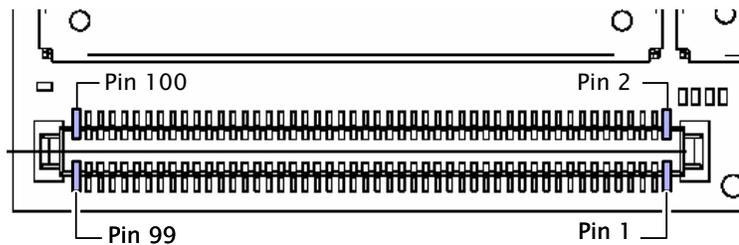


Figure 5.1-1 Wireless modem, viewed from underneath



A mating (host circuit board) connector can be obtained from Panasonic by ordering the following part

100 PIN SOCKET AXK5F00547YG

The following table gives the pin assignments for the system connector interface and a short description for each signal.

Table 5.1-1 Pin Assignments

Pin	Name	Direction	Function	PIN Connection Required
1	GND	-	Ground	Yes
2	VCC	Input	DC power	Yes
3	GND	-	Ground	Yes
4	VCC	Input	DC power	Yes
5	GND	-	Ground	Yes
6	VCC	Input	DC power	Yes
7	GND	-	Ground	Yes
8	VCC	Input	DC power	Yes
9	GND	-	Ground	Yes
10	VCC	Input	DC power	Yes
11	GND	-	Ground	Yes
12	VCC	Input	DC power	Yes
13	CHG_IN	Input	Battery charger power	
14	SIMVCC	Output	1.8V or 3.0V SIM card supply	Yes ¹
15	SIMRST	Output	SIM card reset signal	Yes ¹
16	SIMCLK	Output	SIM card clock signal	Yes ¹
17	SIMDAT	In/Out	SIM card data	Yes ¹
18	SIMDET	Input	SIM presence detection	Yes ¹
19	Reserved	-	-	
20	SERVICE	Input	Flash programming enable signal	
21	PON_H	Input	Device on control	Yes ²
22	Reserved	-	-	
23	Reserved	-	-	
24	Reserved	-	-	
25	Reserved	-	-	
26	Reserved	-	-	
27	ADIN1	Input	ADC Input 1	
28	ADIN2	Input	ADC Input 2	
29	ADIN3	Input	ADC Input 3	
30	ADIN4	Input	ADC Input 4	
31	VRTC	Input	DC supply for real time clock	
32	ALARM	Output	RTC alarm	
33	PON_L	Input	Device on/off control	Yes ²
34	VUSB	Output	USB DC power	Yes ³
35	USBDP	In/Out	USB data positive	Yes ³
36	USBDN	In/Out	USB data negative	Yes ³
37	LED1	Output	LED control	

Pin	Name	Direction	Function	PIN Connection Required
38	LED2	Output	LED control	
39	TX_ON	Output	Transmit indication	
40	GPIO1	In/Out	General purpose IO	
41	GPIO2	In/Out	General purpose IO	
42	Reserved	-	-	
43	GPIO3	In/Out	General purpose IO	
44	GPIO4	In/Out	General purpose IO	
45	GPIO5	In/Out	General purpose IO	
46	Reserved	-	-	
47	Reserved	-	-	
48	GPIO6	In/Out	General purpose IO	
49	GPIO7	In/Out	General purpose IO	
50	GPIO8	In/Out	General purpose IO	
51	GPIO9	In/Out	General purpose IO	
52	BUZZER	Output	Buzzer Output	
53	RI	Output	Ring Indicator	
54	DCD1	Output	Data Carrier Detect (UART1)	
55	DTR1	Input	Data Terminal Ready (UART1)	
56	DSR1	Output	Data Set Ready (UART1)	
57	RTS1	Input	Ready To Send (UART1)	Yes ⁵
58	CTS1	Output	Clear To Send (UART1)	Yes ⁵
59	DTM1	Input	Data To Module from host (UART1)	Yes ⁴
60	DFM1	Output	Data From Module to host (UART1)	Yes ⁴
61	RTS2	Input	Ready To Send (UART2)	
62	CTS2	Output	Clear To Send (UART2)	
63	DTM2	Input	Data To Module from host (UART2)	
64	DFM2	Output	Data From Module to host (UART2)	
65	VREF	Output	Core voltage reference	Yes
66	PCMCLK	In/Out	Serial PCM clock	
67	PCMFS	In/Out	Serial PCM frame synchronization	
68	PCMDTM	Input	Serial PCM data to module from host	
69	PCMDFM	Output	Serial PCM data from module to host	
70	SSPCLK	In/Out	SPI clock	
71	SSPFS	In/Out	SPI frame synchronization	
72	SSPDTM	Input	SPI data to module from host	
73	SSPDFM	Output	SPI data to host from module	
74	MMCCLK	Output	SD/MMC card clock	
75	MMCCMD	In/Out	SD/MMC card command/response	
76	MMCDAT0	In/Out	SD/MMC card data 0	

Pin	Name	Direction	Function	PIN Connection Required
77	MMCDAT1	In/Out	SD/MMC card data 1	
78	MMCDAT2	In/Out	SD/MMC card data 2	
79	MMCDAT3	In/Out	SD/MMC card data 3	
80	MMCMD_EN	Output	SD/MMC card command enable	
81	MMCDAT_EN	Output	SD/MMC card data enable (data 1-3)	
82	MMCDAT_EN0	Output	SD/MMC card data enable (data 0)	
83	KEYROW1	Input	Keyboard row 1	
84	KEYROW2	Input	Keyboard row 2	
85	KEYROW3	Input	Keyboard row 3	
86	KEYROW4	Input	Keyboard row 4	
87	KEYROW5	Input	Keyboard row 5	
88	KEYCOL1	Output	Keyboard row 1	
89	KEYCOL2	Output	Keyboard row 2	
90	KEYCOL3	Output	Keyboard row 3	
91	KEYCOL4	Output	Keyboard row 4	
92	AUXIP	Input	Aux audio to module from host (pos)	
93	AUXIN	Input	Aux audio to module from host (neg)	
94	AUXOP	Output	Aux audio from module to host (pos)	
95	AUXON	Output	Aux audio from module to host (neg)	
96	AREF	-	Analogue reference	
97	MICIP	Input	Microphone input positive	
98	MICIN	Input	Microphone input negative	
99	EARP	Output	Earpiece output positive	
100	EARN	Output	Earpiece output negative	



NOTE

- ¹ – These signals are required if the external SIM interface is used
- ² – At least one of these interfaces is required to be connected
- ^{3,4} – At least one of these interfaces is required to be connected
- ⁵ – These pin connections are required for sleep mode operation

5.2 Dealing with Unused pins

Integrators applications may connect all of the GS64 signals pins, or just those necessary for minimal operation, or most commonly some other permutation. If GR64 signal pins are not connected to the host application you should terminate them in the following manner.

Table 5.2-1 Unused Pin Termination

Pin	Name	Unused pins
1, 3, 5, 7, 9, 11	GND	Must be connected
2, 4, 6, 8, 10,12	VCC	Must be connected
27	ADIN1	Ground
28	ADIN2	Ground
29	ADIN3	Ground
30	ADIN4	Ground
65	VREF	Must be connected
92	AUXIP	Connect to AREF
93	AUXIN	Connect to AREF
97	MICIP	Connect to AREF
98	MICIN	Connect to AREF
All other signal pin may be left open (un-terminated)		

5.3 General Electrical and Logical Characteristics

The electrical characteristics in this document refer to the behavior of the device under specified conditions. Electrical requirements refer to conditions imposed on the user for proper operation of the device.

All IO to and from the GS64 is 1.8V unless otherwise stated. For user applications employing other logic voltage technology it may be necessary to implement level translators on the host-side circuitry in order to achieve level compatibility. To facilitate ease of level conversion the GS64 provides a 1.8V reference on the VREF pin. The VREF voltage from which all 1.8V logic is derived is covered in section 5.6

All input buffers are of the same type and they offer hysteresis of 200 mV—380 mV

The electrical characteristics for 1.8V IO signals are shown in Table 5.3-1

Table 5.3-1 1.8V IO Characteristics

Parameter	Min	Typ	Max	Unit
Input Voltage Low (VIL)	-0.3		0.45	V
Input Voltage High (VIH)	1.16		VREF+0.3	V
Input Current (no pull-up) Low (VIL)			1.0	μA
Input Current (no pull-up) High (VIH)			1.0	μA
Output Low Voltage, 2 mA (VOL)			0.25 x VREF	V
Output High Voltage, -2 mA (VOH)	0.75 x VREF			V
Output 3-State Current Low (IOZL)			10	μA
Input Voltage Low (VIL)	-0.3		0.45	V
Input Voltage Low (VIH)	1.16		VREF+0.3	V

Table 5.3-2 1.8V IO Absolute Maximum Ratings

Parameter	Min	Typ	Max	Unit
Input Withstanding Voltage Low	-0.5			V
Input Withstanding Voltage High			2.3	V



WARNING

Stresses in excess of the voltage withstanding limits can cause permanent damage to the device. These are absolute stress ratings only. Functional operation of the device is not implied at these or any other conditions in excess IO characteristics table. Exposure to absolute maximum ratings for extended periods can adversely affect device reliability.

5.4 Grounds

Pin	Name	Direction	Function
1	GND	-	Ground
3	GND	-	Ground
5	GND	-	Ground
7	GND	-	Ground
9	GND	-	Ground
11	GND	-	Ground
96	AREF	-	Analogue reference

There are two ground connections in the wireless modem, AREF (analogue ground) and GND (digital ground). Pin assignments are shown in the table above.



AREF and GND are connected at a single point inside the wireless modem, however they must not be joined together in the user application.

5.4.1 Analogue Ground (AREF)

AREF is the return signal, or analogue audio reference, for AUXI and AUXO. These two signals provide a single-ended auxiliary audio input (host to module) and output (module to host). AREF is connected to the common GND inside the wireless modem only. The application must not connect GND and AREF.

Parameter	Limit	Unit
Maximum current (I_{MAX})	12.5	mA

5.4.2 Common Ground (GND)

GND is the reference, or return signal, for all system interface digital signals, radio section power, and is also the DC return for the power supply, VCC.

User application circuitry should connect all GND pins together in order to carry the high current drawn by the wireless modem.

Parameter	Per Pin	Total	Unit
Maximum current (I_{MAX})	600	3600	mA
Maximum average current (I_{AVG})	100	600	mA

5.5 Regulated Power Supply Input (VCC)

Pin	Name	Direction	Function
2	VCC	Input	DC power
4	VCC	Input	DC power
6	VCC	Input	DC power
8	VCC	Input	DC power
10	VCC	Input	DC power
12	VCC	Input	DC power

Power is supplied to the wireless modem VCC pins, from an external source.

User application circuitry should connect all VCC pins together in to carry the current drawn by the wireless modem.

The electrical characteristics for VCC are shown in the following table.

Parameter	Mode	Limit
VCC Supply voltage	Nominal	3.6 V
	Min	3.2 V
	Max	4.5 V
	Absolute maximum limit	-0.3V to 6.5V
	Maximum supply ripple	<100mV @<200kHz <20mV @>200kHz
Maximum allowable voltage drop	Transmission burst	200mV
Maximum current consumed	Full power (2W) transmit	2100 mA peak
		340 mA average



Stresses in excess of the absolute maximum limits can cause permanent damage to the device. These are absolute stress ratings only. Functional operation of the device is not implied at these or any other conditions in excess of those given in the normal Min & Max values stated. Exposure to absolute maximum ratings for extended periods can adversely affect device reliability.



TIP

The wireless modem has insufficient internal capacitance to supply the large current peaks during GSM burst transmission – use the following general guidelines in designing the application power supply.

- Fit a low ESR electrolytic capacitor close to the wireless modem ($>1,000 \mu\text{F}$, with an ESR $< 100 \text{ m}\Omega$)
- Ensure power supply to wireless modem line resistance is $< 200 \text{ m}\Omega$



CAUTION

The module has approximately $40\mu\text{F}$ of internal capacitance across the VCC pins. During initial power-up the host power supply will have to charge this capacitance to the operating voltage. This initial in-rush current may exceed the module's normal peak current, sometimes greater than an order of magnitude higher (depending upon the power supply design) for a short duration (generally a few microseconds).

5.6 Voltage Reference (VREF)

Pin	Name	Direction	Function
65	VREF	Input	Core voltage reference

GS64 provides a 1.8V voltage as a reference to the host side device. The VREF reference may be used by legacy users, or users of different interface voltage technology, to implement level-shifter circuits through which IO signals can be safely interconnected.

VREF output

Parameter	Min	Nom	Max	Unit
VREF output voltage	1.74	1.8	1.86	V
VREF load current			20	mA

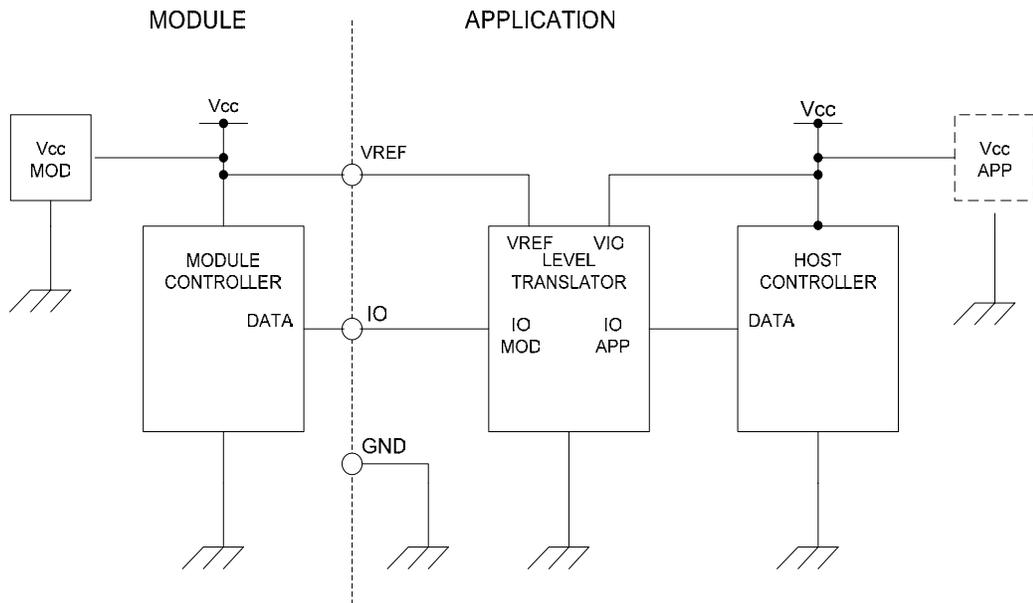


Figure 5.6-1 Typical Level shifter arrangement using VREF

5.7 Battery Charging Input (CHG_IN)

Pin	Name	Direction	Function
11	CHG_IN	Input	Battery charger power

For battery powered applications, the GS64 provides a charge input (CHG_IN) pin to aid and support battery charging. A typical application would power the wireless modem directly from a battery source connected to VCC (pins 2, 4, 6, 8, 10) then provide a dc power source to the CHG_IN connection (pin 11). The GS64 can control an internal switching FET which creates a charging pathway to the battery. While power is provided at CHG_IN, the battery charge can be maintained. If the power should fail or be removed at CHG_IN, the application will be supported by the battery alone. When CHG_IN voltage returns, the battery charging and maintenance will commence once more.

The GS64 module supports only one mode of charging, microprocessor supervised pulsed-charging. Also, the module only supports one battery cell type as standard. Users may, if they wish, develop charging algorithms and control through the Sony Ericsson M2mpower Embedded Applications. Users wishing to attempt charging of battery types not supported by the standard type, indicated in this document, do so at their own risk.



Battery charging algorithms are unique to different battery types. Sony Ericsson Mobile Communications will not accept any responsibility or liability for damage, product failures, even death or injury occurring as a result of incompatible battery and charging algorithms being applied.

Safety considerations must be taken into account when using the battery charge function of the GS64; for example, monitoring the temperature of the battery. If the temperature of the battery exceeds its specification limits, battery charging must be stopped immediately. If the battery temperature continues to rise the application should be suspended or the battery disconnected. Battery temperature can be monitored with a suitable detection circuit, using the GS64 ADC inputs.



When charging Lithium batteries, the battery pack must have an internal protection circuit in accordance with the manufacturer's instructions.

During microprocessor supervised mode, the GS64 takes a current-limited voltage source at the CHG_IN pin to implement constant-current charging of a single Li-Ion cell connected to the VCC pins.

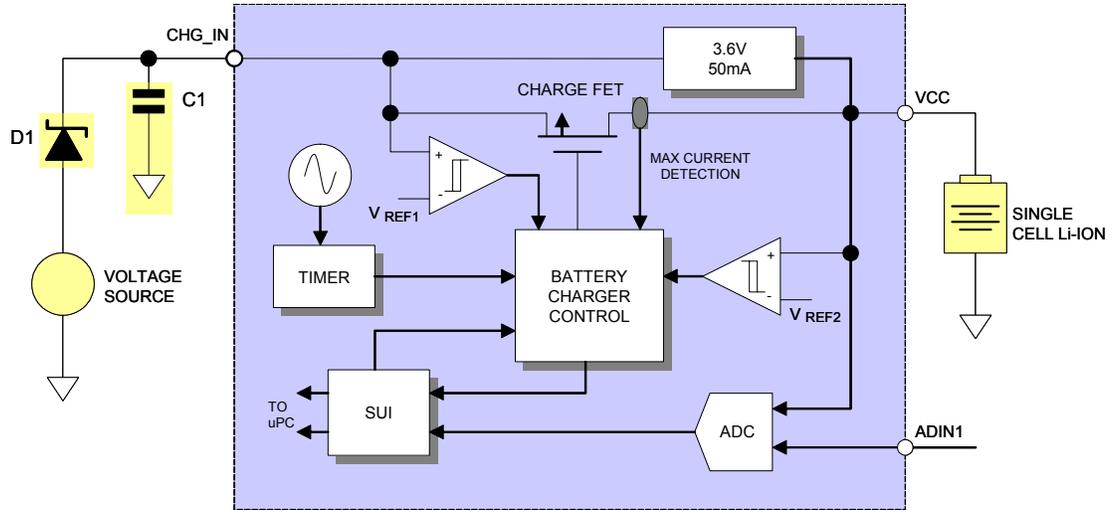


Figure 5.7-1 Typical application for pulse charging a battery

5.7.1 Charging Process

Figure 5.7-1 shows a typical battery charging implementation. The voltage source must be current limited (500 mA max). A reverse current protection diode prevents external fault conditions from draining the battery. A small (typ 10 μ F) capacitor should be placed close to the CHG_IN pin.

In the application shown, a conditioning phase slowly raises the voltage of a deeply discharged cell to a level suitable for fast-charging. After cell conditioning is complete, the microprocessor uses the GS64'S ADC converter to monitor the battery cell's status and uses the power management block to control the charge-FET.

A charge request is initiated when an external voltage source is applied to the CHG_IN pin. However, before this request is passed to the microprocessor, CHG_IN is verified to be greater than VCC by 150 mV, and at least 3.7 V. If the latter criteria is not met, the module limits charging to the conditioning phase. If the former criteria is not met, the charge request is ignored and all charging is disabled. If the CHG_IN voltage exceeds the upper limit of 6.3 V it will be detected by the module, but charging is not inhibited. In this case, however, CHG_IN is outside the normal operating range of the device, so the software will not initiate charging if CHG_IN > 6.3 V is detected.

The delta between CHG_IN and VCC is continuously monitored; however, the valid to invalid detection has a delay of 46 ms. When CHG_IN exceeds VCC by 150 mV, it is considered to be at a valid relative level. It is considered to have an invalid relative level if it subsequently falls below VCC by 50 mV. If the relative voltage of CHG_IN goes invalid and remains invalid for the duration of the detection delay, charging is terminated.

As a safety precaution, the battery cell voltage must be at least 2.5 V before fast-charge is allowed to take place. If the battery cell voltage is less than 2.5 V, it is considered either deeply discharged or shorted. To protect a Li-ion cell from the damage that may occur if it is fast-charged from this state, a 3.6 V trickle-charge source is used to safely condition the battery cell. The conditioning charge current is limited to 50 mA, which for most Li-ion cells is 10% or less of the recommended CC fast-charge current. In most instances, the battery cell voltage will be greater than 2.5 V at the time the charge request is initiated, resulting in the conditioning phase being skipped.



There is always a small chance that the charge management block in the GS64 power management ASIC will malfunction or fail, which could lead to over-charging of the battery. It is strongly recommended that any battery chosen for use with your application has its own additional integrated over-current and over-voltage protection.

5.7.2 Series Diode

When charging is disabled, the potential for rapid cell discharge through the body diode inherent in the Enhancement-mode charging FET, a Schottky diode must be placed in between the external source and the CHG_IN pin. The diode should have a forward current and power dissipation rating consistent with its intended use, and a maximum forward voltage drop of 0.6V.

5.7.3 Battery Selection

Whilst there are several rechargeable battery technologies commercially available, including Nickel Cadmium (NiCd), Nickel Metal Hydride (Ni-MH), Lithium-Polymer (Li-Polymer) and Lithium-Ion (Li-Ion), the only technology recommended and supported for use with the GR64 is Li-Ion. Li-Ion provides a good combination of high energy (3.7v) and long cycle life, which lead to low overall energy cost.

The weight of lithium ion batteries is approximately one half compared with a nickel cadmium or nickel metal hydride battery of similar capacity. The volume of lithium ion batteries is 40 to 50% smaller than that of nickel cadmium, and 20 to 30% smaller than that of a nickel metal hydride.

The lithium ion battery is free from the so-called memory effect, a phenomenon associated with nickel cadmium in which the apparent battery capacity decreases when shallow charge and discharge cycles are repeated.

A single lithium ion cell has a voltage of 3.7V (mean value), which is equal to either three nickel cadmium or nickel-metal hydride cells connected in series. This voltage is close to the nominal VCC of the GS64 device.

Li-Ion batteries generally provide long storage life with few limiting condition, and offer problem-free charge after long storage. Under normal conditions, the lithium ion battery has a life of more than 500 charge/discharge cycles. Also, Li-Ion batteries have a slow self-discharge rate (typically 1.3% per month, compared with Ni-MH batteries which can exceed 50% per month).

Lithium ion batteries are environmentally friendly, inasmuch as they do not contain any heavy metal pollution substances such as cadmium, lead, or mercury.

There are many manufacturers of Li-Ion batteries worldwide. Sony Ericsson make no recommendations with regard to specific vendors, but here are some considerations for GS64 users which may prove to be useful in the selection process and implementation:

- Li-Ion batteries marketed for cellular (mobile) phone use may make a good choice
- battery manufacturers with heritage in supplying the cellular (mobile) phone industry could make a good choice, especially for high-volume requirements
- look carefully for batteries which are rated at temperatures that the GS64 is likely to operate at (many batteries are only specified for -20°C to +65°C operation which may not be sufficient)
- small form-factor (typically handset-sized) Li-Ion battery capacity varies considerably, some batteries are rated as high as 3200mAh (600mAh to 1800mAH are more commonly available)
- weight is generally not a problem with typical GS64 user application, even so small form-factor Li-Ion batteries (up to 1800mAh) can vary between 10 to 40 grams
- size is generally a factor of capacity, since larger capacity batteries naturally have more material/cells, and will range between 2750mm³ to 18000mm³ for small form-factor Li-Ion batteries
- the speed by which lithium-ion ages is governed by temperature and state-of-charge; high temperatures and deep discharge will effect useful life
- if possible avoid frequent full discharges because this puts additional strain on the battery, partial discharges with frequent recharges are better
- never short circuit the terminals of a Li-Ion battery

- do not expose Li-Ion batteries to moisture or rain
- monitor battery temperature during charging using a thermistor placed on or near the battery wired to an ADC input on the module
- Li-Ion batteries have a higher ESR (compared to Ni-Cd or Ni-MH), although this should not be a limiting factor for peak current delivery, any battery should be capable of at least 50% greater than the GS64 demands (~3A pk)

To determine battery life, on a full charge, the following rule of thumb can be applied:

$$\text{Standby time} = \text{Battery Capacity (mAh)} / \text{Idle current (mA)}$$

$$\text{Call time (voice or data)} = \text{Battery Capacity (mAh)} / \text{Call current (mA)}$$

Example 1 - Standby time:

A 600mAh rated Li-Ion battery, from fully charged (around 4.2V) to the module cut-off point (3.2V) will provide around 95% of its total charge capacity. For a standby (idle) current of 18mA, the module will typically provide

$$600 * 0.95 / 18 = 32 \text{ hours standby time}$$

Example 2 - Call time:

An 1800mAh rated Li-Ion battery fully charged, transmitting maximum power on a low-band (850/900MHz) channel may consume an average 320mA, therefore the module would typically provide

$$1800 * 0.95 / 320 = 5 \text{ hours } 20 \text{ mins call time}$$

Example 3 – Typical Operation:

A module performing periodic network data transfers and communicating intervallic status information to its host would spend its non-active periods in sleep mode. If the module spends 30 mins each day on call (320mA), 30 second each hour performing housekeeping, monitoring and status tasks (110mA), and sleeps (2.1mA) during the intervening periods, an 1800mAh rated Li-Ion battery fully charged would typically provide

$$1800 * 0.95 / ([0.5hr * 320] + [0.2hr * 110] + [23.3hr * 2.1]) = 7 \text{ days } 6 \text{ hrs operation}$$



The above examples are given for guidance, the actual battery life will depend upon variables such as battery condition, number of previous charge/discharge cycles, operating temperature, series resistance between battery and the module, and manufacturing tolerances

5.8 Powering the Module ON and OFF (PON_L, PON_H)

Pin	Name	Direction	Function
21	PON_H	Input	Device On/Off control
33	PON_L	Input	Device On/Off control

The GS64 offers two hardware methods to power up and down the module.

The PON_L signal utilizes a momentary switching mechanism to alternate between power-on and power-off sequences. PON_L is held high to VCC by an internal pull-up resistor. The user asserts PON_L by pulling this signal low for a pre-defined period to initiate powering-on of the module. The user re-asserts PON_L with a subsequent low transition, which is held low for a pre-defined period, to power-off the module.

The PON_H signal is designed to be pulled high and maintained high for the power on period. PON_H is held low by an internal pull-down resistor. The user asserts PON_H by pulling this signal high to VCC in order to initiate powering-on of the module, then maintains it constantly high during normal use. A subsequent de-assertion, marked by a transition of PON_H from high to low, and then maintaining the signal low, will initiate the power-off process.

Only one input should be exercised for each Power-on to Power-off event.

5.8.1 VREF as a Power Indicator

Presence of the VREF signal can be used as a useful indicator that power-on has been successfully initiated. The absence of VREF can be used a successful indicator that the power-off sequence is complete.

The initial presence of VREF indicates that the LDOs are powered, however the module will be establishing network connectivity and registration at this point. Communications between the host application and the module can commence shortly thereafter, however completion of the network registration will be sometime afterwards (the period is dependent upon network loading at the time of attempted registration).

Once the power-off sequence has been initiates, shutting-down the LDOs is the last action in the process. The absence of VREF is an indication that network de-registration and shut-down is complete.

5.8.2 Module On & Off Sequence

Figure 5.8-1 shows typical powering-on and powering-off sequences, using the two optional hardware interfaces.

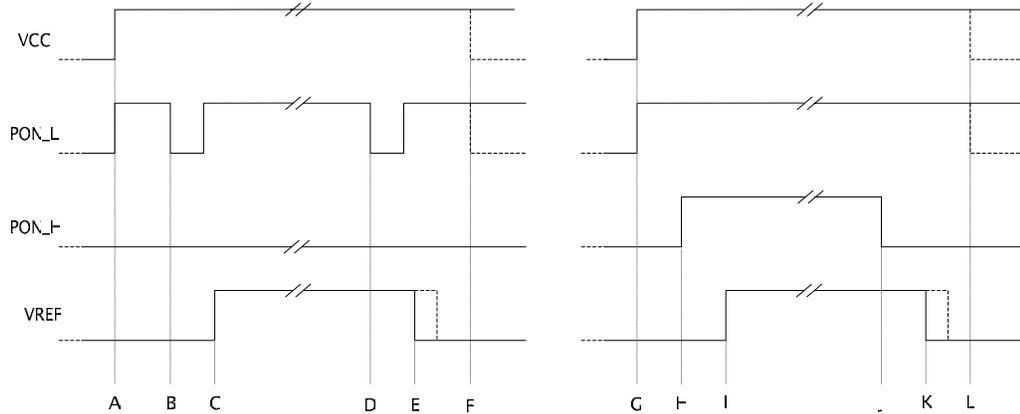


Figure 5.8-1 Typical Power-On & Power-Off Sequences

Event	Description
A	VCC is applied to the module, PON_L is pulled high internally
B	PON_L is pulled low by the user application, initiating a power-on sequence
C	VREF presence indicates a successful power-on initialization
D	PON_L is pulled low by the user application, initiating a power-off sequence
E	VREF absence indicates network de-registration and shut-down complete
F	VCC can be safely removed
G	VCC is applied to the module, PON_H is pulled low internally
H	PON_H is pulled high & retained high, initiating a power-on sequence
I	VREF presence indicates a successful power-on initialization
J	PON_H is released, initiating a power-off sequence
K	VREF absence indicates network de-registration and shut-down complete
L	VCC can be safely removed

5.8.2.1 Power On Timing

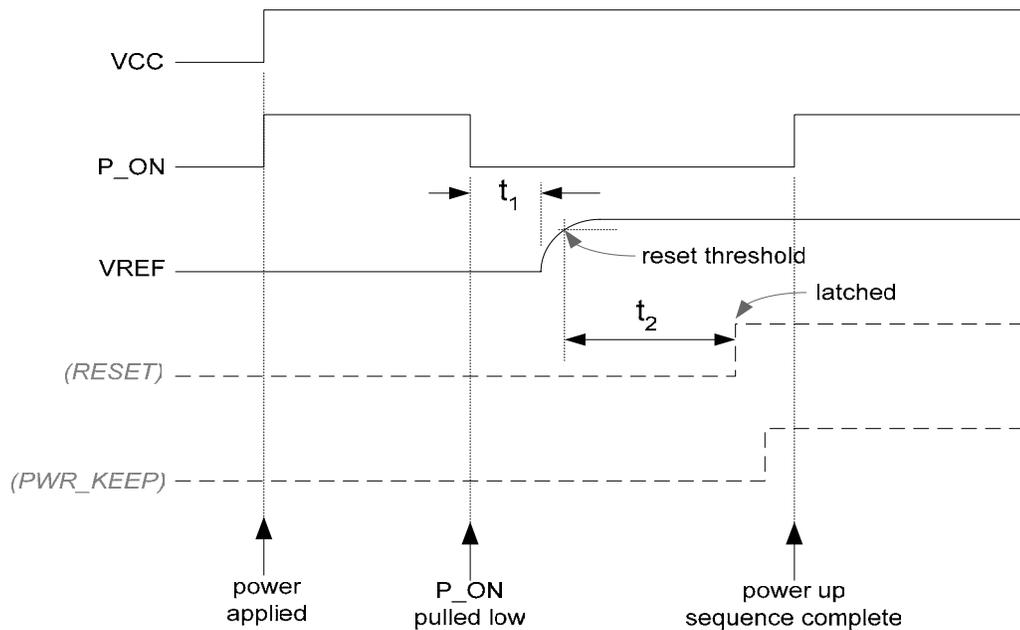


Figure 5.8–2 Power On timing using PON_L as an example

The GS64 power On sequence is shown above using PON_L as an example. The significant signals are VCC, P_ON and VREF, shown by solid lines. The other signals (in dashed lines) are internal to the module and are shown for reference purposes only.

Initially, power is supplied to the VCC pins. The presence of power raises the PON_L through a pull-up resistor to VCC potential. In order to power the module, PON_L is pulled to ground. Once PON_L has been held low for 125ms (denoted by t_1) the primary LDOs power up, including the VREF output. VREF exceeds its reset threshold approx 500 μ s later, then 250ms afterwards (denoted by t_2) the *RESET* line goes high. The microprocessor can latch the power-on state by setting the power keep (*PWR_KEEP*) high after the *RESET* goes high and before the power on (PON_L) signal is released.

It is recommended that P_ON is held low for at least 450ms to guarantee completion of the power up sequence.

The PON_H signal has a similar effect at the point of assertion. The power-on timing sequence is the same, provided PON_H remains high. PON_H has to remain high in order for the module to function.

5.8.3 Turning the Module Off

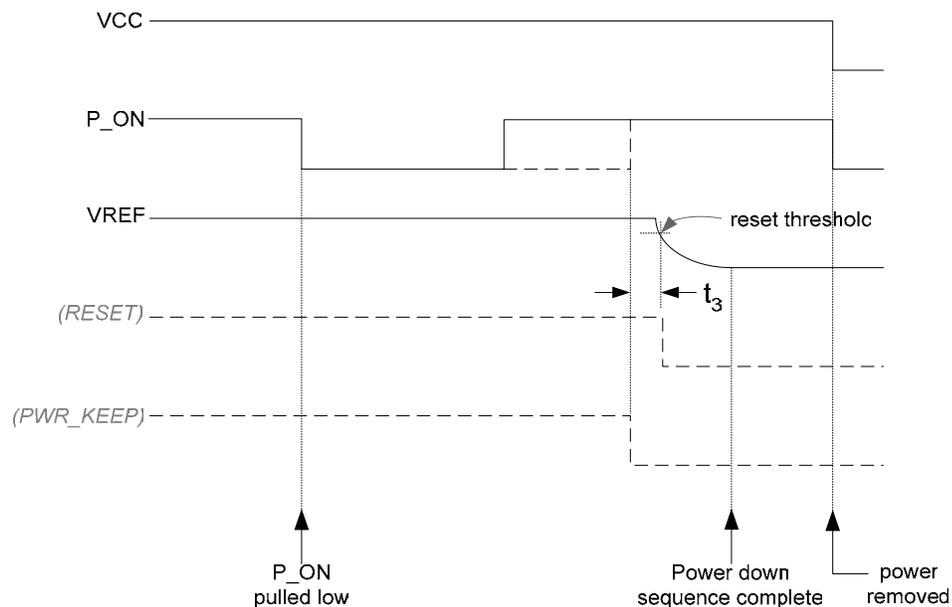


Figure 5.8–3 Power Down timing

The GS64 power down sequence is shown above. The significant signals are VCC, PON_L and VREF, shown by solid lines. The other signals (in dashed lines) are internal to the module and are shown for reference purposes only.

With the module powered normally, PON_L is pulled-up to VCC potential. In order to power down the module, PON_L is pulled to ground. Once PON_L has been held low for at least 125ms the shut-down procedure begins. Although PON_L can be held low for longer, it will delay completion of the shut-down event. If the module is registered on a GSM network, the de-registration process will complete; this may last between 3 to 30 seconds. The power latch (PWR_KEEP) is released and approximately 70ms later the LDO outputs fall, as indicated by the removal of the VREF output. Once VREF is no longer present, the application can safely remove VCC.

In order to turn the module off using the PON_H signal, the signal is released. The power-off timing sequence is the same, provided PON_H remains low.



The RTC can continue to operate even though VCC is removed, provided that a sufficiently charged backup device is connected to the VRTC. Refer to section 5.20.1 for details.

The relevant characteristics of the ON/OFF Power control interface are shown in the table below.

Parameter	Conditions	Min	Typ	Max	Unit	
Input current	PON_L	Input low=0V, VCC=3.6V	-60	-25	-12	μA
		Input high =VCC, VCC=3.6V	0		1	μA
	PON_H	Input low=0V, VCC=3.6V	-1		0	μA
		Input high =VCC, VCC=3.6V	8	20	60	μA

5.9 Analogue Audio

Pin	Name	Direction	Function
92	AUXIP	Input	Differential auxiliary audio to module from host (pos)
93	AUXIN	Input	Differential auxiliary audio to module from host (neg)
94	AUXOP	Output	Differential auxiliary audio to host from module (pos)
95	AUXON	Output	Differential auxiliary audio to host from module (neg)
96	AREF	-	Analogue reference
97	MICIP	Input	Microphone input positive
98	MICIN	Input	Microphone input negative
99	EARP	Output	Earpiece output positive
100	EARN	Output	Earpiece output negative

The analogue audio signals comprise of two audio inputs to the module, and two audio outputs from the module. Both sets of audio interfaces are differential. Analogue audio can be used for various configurations, including a car kit mode, portable hands free and speakerphone (with an additional output gain stage).

Five audio profiles are available for GS64 users to configure various modes of operation. Each profile is factory set to represent different modes, typical of general usage. The customer can modify profiles to optimize acoustic performance to their specific application.

The analogue inputs and outputs share common uplink and downlink chains which are multiplexed, and selectively switched by the user through AT-commands.

There are five factory-set audio profiles as follows:

- portable hands free
- handset
- car kit
- speakerphone
- headset

Portable hands free is the factory-set default profile. The modification, configuration, manipulation and storage of audio profiles is achieved with the AT*E2EAMS (Audio Profile Modification) and AT*E2APR (Audio Profile).

5.9.1 Auxiliary Audio To Mobile Station (AUXIP, AUXIN)

AUXI is a differential auxiliary analogue audio input to the wireless modem. Internally, the signal is routed to the CODEC (COder/DECoder), where it is converted to digital audio and mapped to an internal bus.

All sources must be AC-coupled to avoid attenuation of low frequencies. Use a capacitor greater than the value shown in the table below.

The AUXI input is a passive network followed by the transmit part of the CODEC.

Parameter	Conditions	Min	Typ	Max	Unit
Input voltage full scale	max input gain	142	158	178	mVrms
	min input gain	447	501	564	mVrms
Frequency response	-3dB cut-off	300		3400	Hz
Output dc bias level		2.16	2.4	2.64	V
AC coupling capacitance		1			μ F

5.9.2 Auxiliary Audio From Mobile Station (AUXOP, AUXON)

The auxiliary output is a differential analogue audio output from the wireless modem and may be used to drive a speaker or an earpiece. The interface has an internal 100nF coupling capacitor; a load of 10kohm will provide a near full-scale output capability between 300 to 4300 Hz.

The table below shows the audio signal levels for AUXO.

Parameter	Conditions	Min	Typ	Max	Unit
Output voltage full scale	RL = 10k Ω	670	750	840	mVrms
Frequency response	-3dB cut-off (RL = 10k Ω)	225			Hz

5.9.3 Microphone Signals (MICIP, MICIN)

MICP and MICN are balanced differential microphone input pins. These inputs are compatible with an electret microphone. The microphone contains a FET buffer with an open drain output, which is supplied with at $2.4V \pm 10\%$ relative to ground by the wireless modem as shown below.

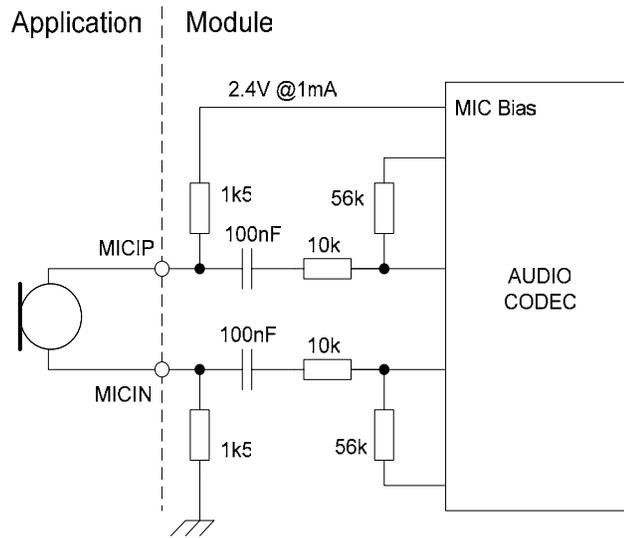


Figure 5.9-1 Microphone connections to the wireless modem

The input low-noise amplifier stage is constructed out of standard low-noise op amps. External resistors set the gain of this stage.

The input gain is scaled by the input resistors to be around 18, which provides optimal performance for many standard types of electret microphones. The module provides a microphone bias at 2.4V, and can supply at least 1mA of current.

Parameter	Conditions	Min	Typ	Max	Unit
Input voltage full scale	max input gain	14	16	18	mVrms
	min input gain	45	50	56	mVrms
Frequency response	-3dB cut-off	300		3400	Hz
Output dc bias level		2.16	2.4	2.64	V

5.9.4 Speaker Signals (EARP, EARN)

EARP and EARN are the speaker output signals. These are differential-mode outputs. With a full-scale PCM input to the CODEC, 0 dB audio output gain setting, and a differential load $R_L = 30\Omega$, the output voltage between EARP and EARN is 1.5 V rms. For load resistances less than 30Ω , the full-scale output needs is limited using the modules internal programmable gain attenuator.

The electrical characteristics are given in the table below.

Parameter	Conditions	Min	Typ	Max	Unit
Input voltage full scale	$R_L = 30\Omega$	1.34	1.5	1.68	Vrms
	$R_L = 16\Omega$	1.41			Vrms
	$R_L = 8\Omega$	1.24			Vrms
Frequency response	-3dB cut-off	300		3400	Hz

5.10 PCM Digital Audio (SSP)

Pin	Name	Direction	Function
66	PCMCLK	In/Out	Serial PCM clock
67	PCMFS	In/Out	Serial PCM frame synchronization
68	PCMDTM	Input	Serial PCM data to module from host
69	PCMDFM	Output	Serial PCM data from module to host

The SSP (Synchronous Serial Port) digital interface is configured to provide a PCM (digital) audio interface. This interface can be used to process PCM digital audio signals as an alternative to routing signals to the CODECs through the analogue uplink and downlink chains.

5.10.1 PCM Data Format

The PCM digital audio interface for GS64 is based upon the Texas Instruments SSI standard. The SSP is a versatile interface which can be programmed for different clock rates and data frame sizes between 4 to 16 bits.

PCMCLK (bit clock) and PCMSYNC (frame synchronization) are both generated by the DSP within the wireless modem. The DSP within the wireless modem in this instance is the master for all external PCM, so clocks and data from external devices must be synchronized to it.

For standard GSM voice a 13-Bit PCM data word is embedded in a 16-bit word frame, as shown in Figure 5.10-1 below.

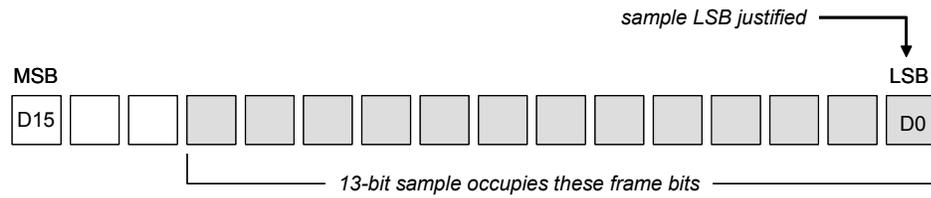


Figure 5.10-1 Typical 16-bit PCM Voice Sample Word Format

Typical PCM data transfer is shown in the following figures.

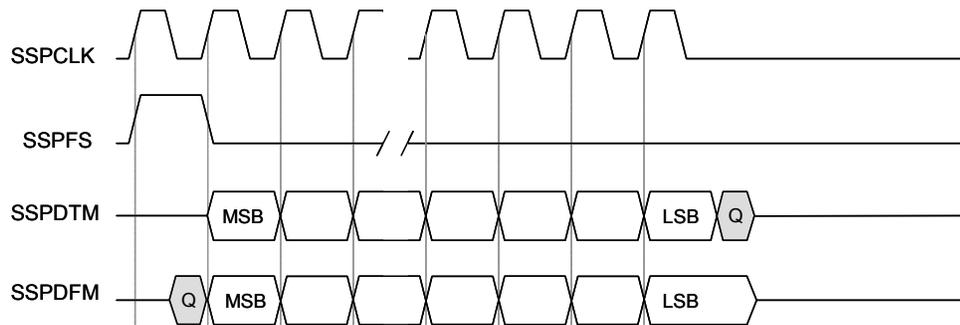


Figure 5.10-2 PCM Frame format for a single transfer

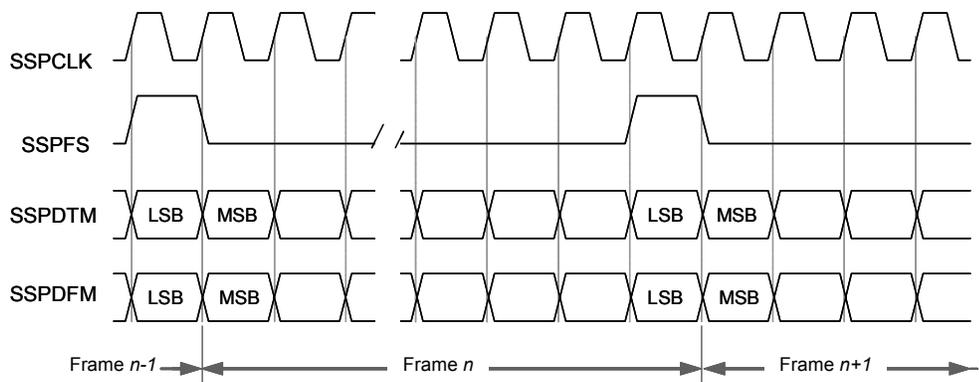


Figure 5.10-3 PCM Frame format for a continuous transfer

5.11 Serial Data Interfaces

The serial channels consist of two UARTs and a USB port. These provide communication links to the application or accessory units.

The serial channels can be used in differing configurations, depending upon the users requirements and application. In practice, both UARTs can be configured as either the control interface or the logging interface. Similarly, control and logging can be carried out simultaneously on the USB interface. However, the common (default) configuration options are described:

- UART1 has full RS-232 functionality and is used for all on- and off -line communication (modem sleep & wake functional control is an integral component of this interface). Its intended use is that of the primary command (AT) interface.
- UART2 behaves as a general-purpose serial data link. It can be used for data logging and de-bugging purposes. It can also be used as a data interface to peripheral devices, such as a GPS receiver.
- The USB port provides a convenient general purpose peripheral (slave) port for use with host devices which have USB controllers.

5.11.1 UART1

Pin	Name	Direction	Function
53	RI	Output	Ring Indicator
54	DCD1	Output	Data Carrier Detect (UART1)
55	DTR1	Input	Data Terminal Ready (UART1)
57	RTS1	Input	Ready To Send (UART1)
58	CTS1	Output	Clear To Send (UART1)
59	DTM1	Input	Data To Module from host (UART1)
60	DFM1	Output	Data From Module to host (UART1)
56	DSR1	Output	Data Set Ready (UART1)

UART1 is a full featured Universal Asynchronous Receiver Transmitter providing full-duplex asynchronous communication.

UART1 has the following features :

- 32 bytes of FIFO for both receive and transmit
- FIFO threshold interrupts
- 1 start bit, 7 or 8 data bits, 1 optional parity bit, 1 or 2 stop bits
- Programmable baud rate
- Auto-configuration mode with auto-baud and auto-format operation
- Hardware flow control
- Software flow control.

UART1 signals replicate a 9-pin RS232 (V.24) serial port. However, UART1 signal levels are not compliant with the RS232 (V.28) standard. Conversion between the wireless modem CMOS levels and RS232 levels can be achieved using a standard interface IC, such as the Maxim Integrated Products MAX3237. The relationship between the levels is shown in the table below.

DTM, DFM	RI,RTS,CTS,DSR,DTM,DCD	RS232 level	GS64 level
1	OFF	<-3V	VREF-0.4V
0	ON	>+3V	0.4V

5.11.2 Serial Data Signals (DTM1, DFM1)

The default baud rate of the UARTs is auto-baud. Baud rates of between 600 bauds to 460 kbauds are possible. The wireless modem also supports 3GPP TS27.010 multiplexing protocol, which starts when the appropriate command is sent.

5.11.2.1 Serial Data From Wireless modem (DFM1)

DFM1 is an output signal that the wireless modem uses to send data via UART1 to the host application.

5.11.2.2 Serial Data To Wireless modem (DTM1)

DTM1 is an input signal, used by the application to send data via UART1 to the wireless modem.

5.11.3 Control Signals (RTS1, CTS1, DTR1, DSR1, DCD1, RI)

Depending upon the user application, some, all, or none of the control signals may be needed. Each of the control signals can alternatively be configured as a general purpose IO. When hardware flow control is not used in communications between the application and the wireless modem, some applications may require RTS and CTS to be connected to each other at the wireless modem. Users should familiarize themselves with the specific implementation of their UART.

UART1 converted signals, together with GND, DTM1 and DFM1 form a 9-pin RS232 data port.

5.11.3.1 Hardware flow control RTS1 and CTS1

RTS and CTS provide a hardware flow control mechanism.

5.11.3.2 Request to Send (RTS1)

RTS is used to condition the DCE for data transmission. The default level is high by internal pull up. The application must pull RTS low to enable data transmission from the wireless modem. Similarly, the wireless modem asserts CTS low, indicating it is ready to receive data transmission from the host.

5.11.3.3 Clear To Send (CTS1)

CTS is asserted by the DCE to indicate that the host (DTE) may transmit data. When CTS is high, the host (DTE) is not permitted to transmit data. The table below shows the load characteristics for this signal.

5.11.3.4 Data Terminal Ready (DTR1)

DTR indicates that the DTE is ready to receive data. It also acts as a hardware 'hang-up', terminating calls when switched high. The signal is active low. Users can define the exact behavior of DTR with an the AT&D command.

5.11.3.5 Data Set Ready (DSR1)

DSR indicates that the DCE is ready to receive data. The signal is active low. Behavior is controlled using the AT&S command.

5.11.3.6 Data Carrier Detect (DCD1)

DCD indicates that the DCE is receiving a valid carrier (data signal) when low. Behavior is controlled using the AT&C command.

5.11.3.7 Ring Indicator (RI)

RI indicates that a ringing signal is being received by the DCE when toggled low. Users can define the exact behavior of RI with an AT command, including the option of asserting the RI signal to flag an incoming SMS by using the AT*E2SMSRI command.

5.11.4 UART2 (DTM2, DFM2)

Pin	Name	Direction	Function
61	RTS2	Input	Request To Send (UART2)
62	CTS2	Output	Clear To Send (UART2)
63	DTM2	Input	Data To Module from host (UART2)
64	DFM2	Output	Data From Module to host (UART2)

UART 2 consists of a full duplex serial communication port with transmission, reception lines and hardware flow control.

Timing and electrical signals characteristics are the same as for UART1, DTM1 and DFM1, including the baud rate range and the capability to auto-baud.

5.11.4.1 Transmitted Data (DTM2)

DTM2 is used by the application to send data to the wireless modem via UART2. It has the same electrical characteristics the equivalent signal in UART1.

5.11.4.2 Received Data (DFM2)

DFM2 is used to send data to the application via UART2. It has the same electrical characteristics as the equivalent signal in UART1.

5.11.4.3 Request to Send (RTS2)

RTS is used to condition the DCE for data transmission. It has the same electrical characteristics as the equivalent signal in UART1.

5.11.4.4 Clear To Send (CTS2)

CTS is asserted by the DCE to indicate that the host (DTE) may transmit data. It has the same electrical characteristics as the equivalent signal in UART1.

5.11.5 USB

Pin	Name	Direction	Function
35	USBDP	In/Out	USB data positive
36	USBDN	In/Out	USB data negative
34	VUSB	Input	USB DC power

The USB interface is compliant with the USB2.0 standard for a full speed (12Mbps) endpoint device. Together with VUSB (the USB transceiver DC power) and GND it creates a standard USB 4-pin interface. VUSB (VBUS in the USB standard) is nominally 5.0V.

The USB interface has the following features

- Full-speed (12 Mbits/s) device operation
- 16 unidirectional endpoints
- Each endpoint capable of supporting control, interrupt, isochronous and bulk transfer
- Programmable endpoint types and FIFO sizes and internal 1120-byte logical (2240-byte physical for dual-packet mode) shared FIFO storage allow a wide variety of configurations.
- Dual-packet mode of FIFOs reduces latency
- USB reset can be programmed to clear device address.
- Firmware ability to wake up and reset a suspended device
- 8, 16, 32, and 64-byte FIFO sizes for non-isochronous transfers
- 64, 256, 512, and 1024-byte FIFO sizes for isochronous transfers
- Firmware downloading
- Trace debug port for module diagnostics

The USB interface supports 3GPP TS 27.010 multiplexing, and may be used as the primary AT-command interface.

Internally, the USBDP line is pulled up by a 1.5K resistor, in accordance with the USB standard, to indicate that it's a full-speed capable device to the USB controller.

To implement successful applications using the GS64 USB interface, users should familiarize themselves with the USB specification.

5.11.6 SIM Card Interface

Pin	Name	Direction	Function
14	SIMVCC	Output	1.8V or 3.0V SIM card supply
15	SIMRST	Output	SIM card reset signal
16	SIMCLK	Output	SIM card clock signal
17	SIMDAT	In/Out	SIM card data
18	SIMDET	Input	SIM presence detection

This interface allows the user to communicate with the smart (SIM) card in the user application. The GS64 offers alternative arrangements for accessing the SIM depending on which variant of the GS64 is used. Both variants provide this interface through the system connector, referred to as the *external* or *remote* SIM interface to distinguish it from the integrated SIM interface.

The maximum distance between the SIM card holder and the wireless modem is 70cm. SIM holders placed further than this distance may not meet the SIM interface performance specification.

This SIM interface allows the use of 3 V and 1.8 V SIM cards. The module does not support 5V SIM cards. The wireless modem automatically detects the SIM type, switching the signal voltages accordingly. SIM voltage levels, as shown in the following table, are dependent on the type of SIM card detected by the wireless modem.

Signal	Parameter	Mode	Min	Typ	Max	Unit
SIMVCC	SIM supply voltage	1.8V	1.71	1.8	1.89	V
		3.0V	2.75	2.9	3.05	V
	Short circuit current		10		50	mA
	Quiescent Supply Current	3.0V		20		μA
	Output Capacitance		0.3		2	μF
	Output Capacitor ESR		0.01		1.0	Ω
SIMDAT	High level input voltage (V _{IH})	1.8V			0.7xSIMVCC	V
		3.0V			0.7xSIMVCC	V
	Low level input voltage (V _{IL})	1.8V	0.2xSIMVCC			V
		3.0V	0.4			V
	High level output voltage (V _{OH})	1.8V	0.8xSIMVCC			V
		3.0V	0.8xSIMVCC			V
	Low level output voltage (V _{OL})	1.8V			0.4	V
		3.0V			0.4	V

Signal	Parameter	Mode	Min	Typ	Max	Unit
SIMCLK	High level output voltage (V_{OH})	1.8V	0.9xSIMVCC			V
		3.0V	0.9xSIMVCC			V
SIMRST	Low level output voltage (V_{OL})	1.8V			0.4	V
		3.0V			0.4	V

5.11.7 SIM Detection (SIMDET)

SIMDET is used to determine whether a SIM card has been inserted into or removed from the SIM card holder. You should normally wire it to the ‘card inserted switch’ of the SIM card holder, but different implementations are possible.

When left open, an internal pull-up resistor maintains the signal high and means ‘SIM card missing’ to the wireless modem. When pulled low the radio device assumes a SIM card is inserted. SIMDET is a Digital IO signal.



In order to meet regulatory approval requirements, the SIMDET function must be implemented in the host application.

5.12 Synchronous Serial Port (SSP) Interface [to be implemented in a future release]

Pin	Name	Direction	Function
70	SSPCLK	In/Out	SPI clock
71	SSPFS	In/Out	SPI frame synchronization
72	SSPDTM	Input	SPI data to module from host
73	SSPDFM	Output	SPI data to host from module

The SSP interface provides a synchronous serial peripheral interface based on the Motorola SPI protocol.

The SSPI interface operates in a single master mode only, with the module acting as master. Four clock rates are supported through programming; 1.5MHz, 800kHz, 400kHz, 200kHz. The interface supports a variable word size, between 4bits to 16 bits. Continuous Transfer modes are not supported.

The SSP supports programmable data sizes of 4 bits to 16 bits, in addition to which the polarity of the clock signal to the SPCLK pin is programmable through a register.

5.13 Memory Card Interface (SD/MMC) [to be implemented in a future release]

Pin	Name	Direction	Function
74	MMCCLK	Output	SD/MMC card clock
75	MMCCMD	In/Out	SD/MMC card command/response
76	MMCDAT0	In/Out	SD/MMC card data 0
77	MMCDAT1	In/Out	SD/MMC card data 1
78	MMCDAT2	In/Out	SD/MMC card data 2
79	MMCDAT3	In/Out	SD/MMC card data 3
80	MMCMD_EN	Output	SD/MMC card command enable
81	MMCDAT_EN	Output	SD/MMC card data enable (data 1-3)
82	MMCDAT_EN0	Output	SD/MMC card data enable (data 0)

SD/MMC interface module acts as either a multimedia card bus host or a secure digital memory card bus host. The interface conforms to the following standards:

- Multimedia Card Specification v2.11
- Secure Digital Memory Card Physical Layer Specification v0.96

The SD/MMC interface provides around 800kbps net throughput.

The SD/MMC interface, like all IO in the module, is 1.8V. In order to interface to some SD/MMC devices based on 3V technology it is necessary to level shift these signals for compatibility purposes. The MMC MD & DAT enable signals (pins 80, 81, 82) are provided to configure level shifters for directivity, which may be used with the Agere PSC2217 level shifter for example. There are other means of level shifting using bi-directional level shifters which do not require direction pins, such as:

- Philips GTL2002, 2-bit bidirectional low voltage translators
- Maxim MAX3001E, 8-channel bidirectional level translators

5.13.1 Multimedia Card System

The multimedia card system transfers commands and data using three signal lines on a single physical bus:

- MMCCLK: One bit is transferred on both command and data lines with each clock cycle. The clock frequency varies between 0 MHz and 20 MHz for a multimedia card.

- MMCCMD: Bidirectional command channel that initializes a card and transfers commands. CMD has two operational modes; open-drain for initialization and push-pull for command transfer. This depends on speed requirements for the command channel during the initialization phase; external open-drain pull-up resistor may be needed if the 200 k Ω internal pull-up resistor is too large.
- MMCDAT: Bidirectional data channel, operating in push-pull mode.

5.13.2 Secure Digital Memory Card System

The secure digital memory card system consists of the host and cards connected in a star topology. Multimedia cards and secure digital memory cards can be used in the same system. The power supply can be provided by the host or level-shifter devices such as Agere's PSC2217.

The following signals are used on the secure digital memory card bus:

- MMCCLK: Host to card clock signal.
- MMCCMD: Bidirectional command/response signal (one per card if multiple cards are connected to the bus, in which case, bus multiplexing logic is required).
- MMCDAT[3:0]: Bidirectional data signals (one set per card).
- VDD, VSS: Power and ground signals provided by the host or level translator product.

The MCI (Multimedia Card Interface) does not contain bus multiplexing logic. If more than one secure digital memory cards needs to be supported, the user must implement bus multiplexing logic with external components.

5.14 Service/Programming

Pin	Name	Direction	Function
20	SERVICE	Input	Flash programming enable signal

The SERVICE interface is a standard IO, configured internally as an Input. This input is activated in order to enable flash memory programming. The SERVICE interface is normally pulled HIGH and is made active by the host application pulling it LOW.



NOTE

There are two methods for updating the firmware in the GR64: Sony Ericsson Emma III and Updater. The Emma III system is a web based tool that accesses a Sony Ericsson server from which signed software can be downloaded. The Updater is a local application that downloads a signed image provided by SEMC.

5.15 LED [to be implemented in a future release]

Pin	Name	Direction	Function
37	LED1	Output	LED control signal
38	LED2	Output	LED control signal

The LED driver interface is able to operate single LEDs or a series of LEDs (such as LED backlighting). The LED interfaces are driven by programmable current sources, designed to control the brightness of the LEDs connected to them (typical of keyboard or LCD illumination).

LED1 can be programmed to sink up to 75mA or 150mA in nonlinear steps over two ranges of output. LED2 can be programmed to sink from up to 50mA or 100mA in nonlinear step over two ranges of outputs. Both LED drivers are capable of sinking their maximum output current at a worst-case maximum output voltage of 0.4 V. For efficient use, the LEDs should be forward connected between the main battery and their corresponding LED driver output.

The LED drivers require no supporting components, eliminating the need for current-limiting resistors. The LED outputs should be programmed to values consistent with their rated values. If desired, both LED outputs can be ganged together to provide a maximum single LED driver sink capability of 250mA.

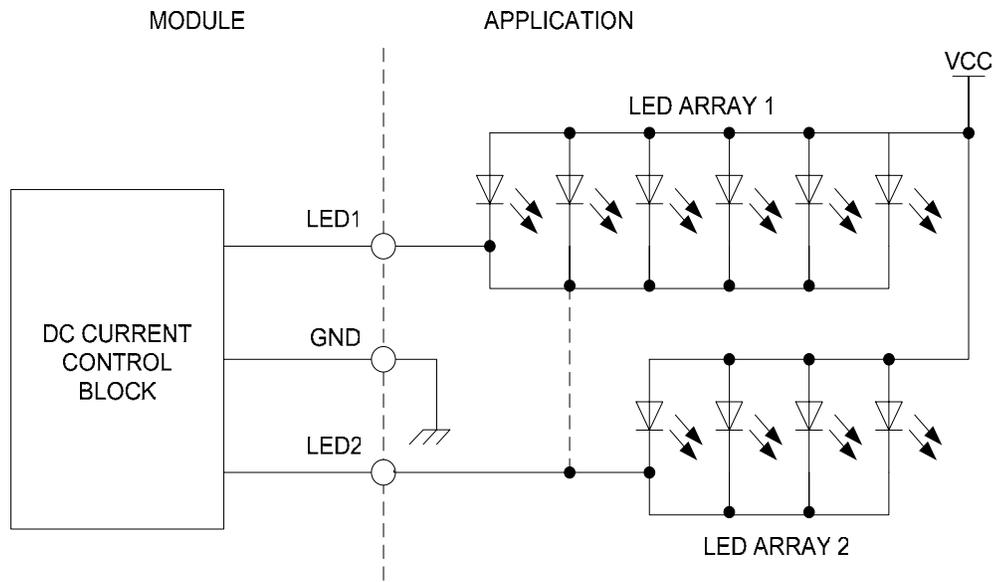


Figure 5.15-1 Typical circuit for LEDs

5.16 General Purpose IO

All general purpose IO (GPIO) is programmable by the user. Some GPIO signals are dedicated, other GPIO can be configured as an alternative to other signal functionality if it is not required by the user. GPIO which has alternate functionality is effectively multiplexed, so that the user chooses through AT commands the appropriate configuration for their application.

Dedicated IO

Pin	Name	Default	Alternate Function
40	GPIO1	GPIO1	None
41	GPIO2	GPIO2	None
43	GPIO3	GPIO3	None
44	GPIO4	GPIO4	None
45	GPIO5	GPIO5	None
48	GPIO6	GPIO6	None
49	GPIO7	GPIO7	None
50	GPIO8	GPIO8	None
51	GPIO9	GPIO9	None

Configurable IO

Pin	Name	Default	Alternate function
74	GPIO10	MMCLK	SD/MMC card clock
75	GPIO11	MMCCMD	SD/MMC card command
76	GPIO12	MMCDAT0	SD/MMC card data
77	GPIO13	MMCDAT1	SD/MMC card data
78	GPIO14	MMCDAT2	SD/MMC card data
79	GPIO15	MMCDAT3	SD/MMC card data
80	GPIO16	MMCMD_EN	SD/MMC card command enable
81	GPIO17	MMCDAT_EN	SD/MMC card data enable (1-3)
82	GPIO18	MMCDAT_EN0	SD/MMC card data enable (0)
83	GPIO19	KEYROW1	Keyboard row 1
84	GPIO20	KEYROW2	Keyboard row 2
85	GPIO21	KEYROW3	Keyboard row 3
86	GPIO22	KEYROW4	Keyboard row 4
87	GPIO23	KEYROW5	Keyboard row 5
88	GPIO24	KEYCOL1	Keyboard row 1
89	GPIO25	KEYCOL2	Keyboard row 2
90	GPIO26	KEYCOL3	Keyboard row 3
91	GPIO27	KEYCOL4	Keyboard row 4

Regular (dedicated) IO and alternate function IO have exactly the same characteristics and can be programmed in the same way. The use of alternate function IO is subject to some degree of limitation:

- Signals which are assigned SD/MMC functionality are controlled by a single register bit so that all nine signals are allocated to either memory card or GPIO; it not possible individually allocate function.
- Signals which are assigned keyboard functionality can be re-allocated GPIO functionality on a pin-by-pin basis, providing anything from 1 to 9 additional GPIO.
- Signals defined as keyboard functions are programmed to generate interrupts, however the same pins programmed as GPIO do not have interrupt capability associated with them.

GPIO is programmable for the following features

- either an input or output
- level-sensitive or transition-sensitive
- open drain or direct drive
- polarity (inversion)
- internal pull-up resistors

Signal labeled in the *Configurable IO* table which are not being used for the indicated alternative function be used as general purpose inputs or outputs; they are not constrained to work in only one direction.

GPIO has a number of sharing (configuration) options. Sharing means that it is not feasible to operate all the alternative features concurrently, however, with care, dynamic switching from one feature to another is possible.

5.16.1 Embedded Applications

When a particular IO feature is required, the user sets the state of the relevant IO blocks by disabling one set before enabling others.

The wireless modem checks the state of the IO when the user requests a new function. The new function is rejected if the current function is not released first.

The states of GPIO n to GPIO m are retained for the next power up. For example, inputs remain as inputs and outputs remain as outputs. The voltage of a defined output pin will still drop to 0 Volts in the wireless modem power down state.

5.17 Keyboard Signals (KEYROW, KEYCOL)

Pin	Name	Direction	Default Function
83	KEYROW1	Input	Keyboard row 1
84	KEYROW2	Input	Keyboard row 2
85	KEYROW3	Input	Keyboard row 3
86	KEYROW4	Input	Keyboard row 4
87	KEYROW5	Input	Keyboard row 5
88	KEYCOL1	Output	Keyboard row 1
89	KEYCOL2	Output	Keyboard row 2
90	KEYCOL3	Output	Keyboard row 3
91	KEYCOL4	Output	Keyboard row 4

The keyboard interface consists of 9 programmable IO pins that are configured for use in scanning a keyboard/keypad. The maximum sized keyboard matrix achievable is 5 x 4. Keyboard inputs must be active for a selectable minimum pulse-width before interrupt generation occurs in the key-press detection process.

Pins that are not needed for the keyboard can be used as programmable IO, as described in section 0.

The default keyboard configuration is shown in the *Default Function* column of the table above. Users wishing to configure the keyboard interface differently or as GPIO should obtain a separate Application Note describing keyboard and GPIO programming from Sony Ericsson through Customer Support.

5.18 Analogue to Digital Converters (ADIN1, ADIN2, ADIN3, ADIN4)

Pin	Name	Direction	Function
27	ADIN1	Input	ADC Input 1
28	ADIN2	Input	ADC Input 2
29	ADIN3	Input	ADC Input 3
30	ADIN4	Input	ADC Input 4

The module has a single precision 10-bit ADC, shared by a number of functions within the module and also through the external interface connections. The ADC sharing arrangement is shown below.

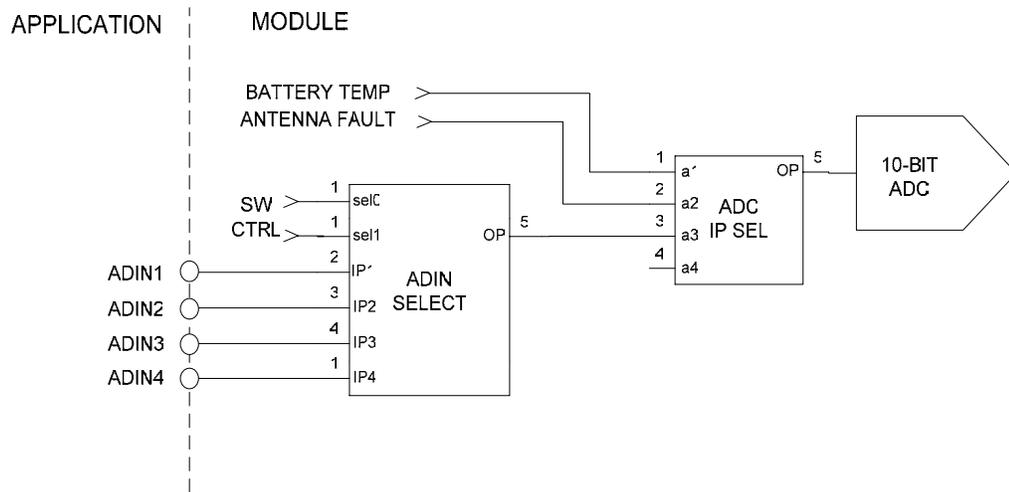


Figure 5.18-1 ADC sharing arrangement

ADC sampling frequency and sampling source selection can be set up and controlled with AT-commands by the user. ADC samples requires up to 5 clock (ADCLK) cycles to process. The ADC also performs some system-level sampling. These two factors limit the maximum practical sampling rate to around 12ksp/s.

Table 5.18-1 ADC Interface Characteristics

Parameter	Condition	Min	Typ	Max	Unit
Resolution			10		bit
Coding: Unsigned Magnitude		000		3FF	Hex
Differential Nonlinearity		-1		1	lsb
Integral Nonlinearity		-10		10	lsb
Full-scale Error		-3		3	%
Offset Error		-14		14	lsb
Conversion Gain*			421		lsb/V
Conversion Intercept*			-9		lsb
Low-level Input Voltage	ADC output=000h				
High-level Input Voltage	ADC output=3FFh	2.45		2.59	V
ADC Clock (ADCLK)		260	325	390	kHz
ADC Conversion Time			12		ADCLK
ADC Sample Delay				5	ADCLK

5.19 Burst Transmission (TX_ON)

Pin	Name	Direction	Function
39	TX_ON	Output	Transmit indication

Burst transmission is the period during which the GSM transceiver is transmitting RF signals. TX_ON is an indicator that the module is transmitting.

A typical application may use TX_ON to blank adjacent receiver circuitry as a means of protecting sensitive input stages.

5.20 Real Time Clock

The real-time clock (RTC) is driven by a 32.768 kHz clock from an internal crystal oscillator. The clock is divided by 32,768 to generate a clock with a 1 second period that increments a 29-bit seconds counter. In addition, it can generate interrupts at a programmed time. The following are the features of RTC:

- 17-year time interval with 1 second resolution.
- Programmed time alarm interrupt
- Alarm output pin

An RTC alarm can be set by using the AT-command AT+CALA.

The RTC relies on an uninterrupted 1.5 V (nominal) power supply (VRTC), whether the module is powered off or on. The RTC alarm operates from the VRTC supply, and therefore utilize 1.5 V logic. Users have the responsibility to provide a backup battery to provide uninterrupted VRTC function when the module is powered down.

RTC Accuracy

Parameter	Condition	Max	Unit
RTC accuracy	Ambient (+25±2°C) operation	52.6	Secs/month
RTC accuracy	Extreme temperatures	65.2	Secs/month

5.20.1 Real Time Clock Backup Supply (VRTC)

Pin	Name	Direction	Function
31	VRTC	Input	DC supply for real time clock

VRTC provides an input connection to the module which allows the user to power the real time clock (RTC) within the GS64 by way of a coin cell or charged capacitor.

When the module is powered, an internal LDO regulator provides a 200 μ A source designed to supply the microprocessor's RTC block. It is also intended to recondition a rechargeable coin cell that supplies the RTC module when the main battery is removed, or has insufficient energy. Because this LDO is always on, even when the module is powered down, it features very low quiescent current. It also offers reverse current protection, with low leakage, when the coin cell is powering the RTC block.

The RTC LDO is primarily designed to charge manganese–silicon lithium batteries. Rechargeable coin cells with different chemical composition may also be charged, provided their charging requirements are consistent with the RTC LDO's electrical characteristics. The VRTC output is nominally 1.5 V.

VRTC LDO characteristics

Parameter	Condition	Min	Typ	Max	Unit
Output Voltage Tolerance	IOUT = 10 μ A	1.45	1.5	1.55	V
Maximum Output Current		200			μ A
Short-circuit Current Limit	VRTC to GND	0.7	1.6	2.9	mA
Output Resistance	IOUT = 10 μ A	75	100	150	Ω
Line Regulation	IOUT = 10 μ A			5	mV
Off Reverse Leakage Current			0.1	1	μ A

In the backup condition the RTC block will function to as low as 1.1V on the VRTC pin. The RTC draws 10 μ A typically during powered backup (15 μ A max).

Figure 5.20–1 shows the VRTC connectivity arrangement.

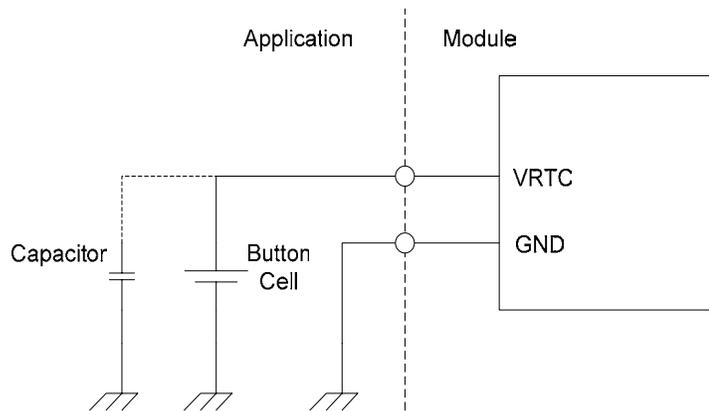


Figure 5.20-1 VRTC connection

5.20.2 RTC Alarm (ALARM)

Pin	Name	Direction	Function
32	ALARM	Output	RTC Alarm

The Alarm output is logic output from the module which is supplied from the RTC circuitry block. This block is in turn supplied either from the main supply of the module or from a backup battery if the main supply is not available.

5.20.2.1 ALARM Output from the Module

The ALARM time is set by the use of an AT-command. The output is normally at VRTC level and will go low for one second when the ALARM becomes active.

Since the VRTC interface is operable down to 1.1V, transistor circuitry must be used on the host side. It is recommended that integrators use an FET to minimize current consumption. If a suitable FET, operating at the low voltage necessary, cannot be found then bi-polar must be used. The resistors shall be kept as high impedance as possible to minimize current consumption.

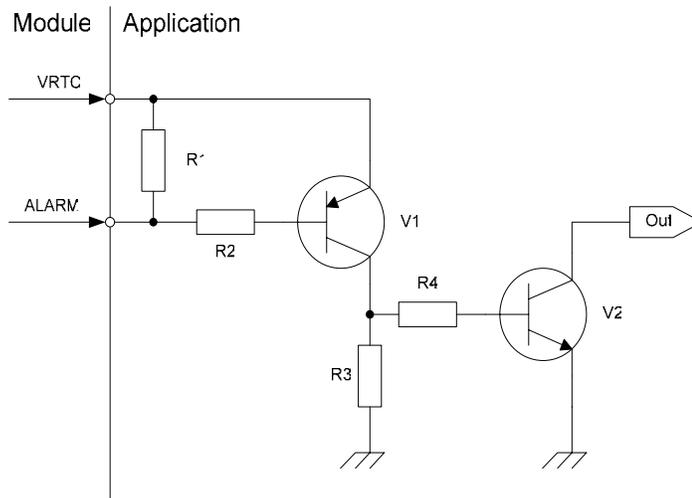


Figure 5.20-2 Typical host-side circuit for ALARM output

VRTC is specified to work down to 1.1V across the environmental operating conditions of the GS64. Integrators may discover in controlled environments that the VRTC interface will function reliably as low as 0.8V, so best practice would be to design the circuitry to operate down to 0.7V.

5.20.3 ALARM Utilization as a Wake-up

The ALARM output can be used by the host application to wake up from standby or hibernation mode, but it can also be used to completely power up the host application. The example below shows how the ALARM output (marked *Out* on Figure 5.20-2, and *In* on Figure 5.20-3) triggers the enabling of the main power to the application. The application has a parallel hold transistor (V4), and a Start Button.

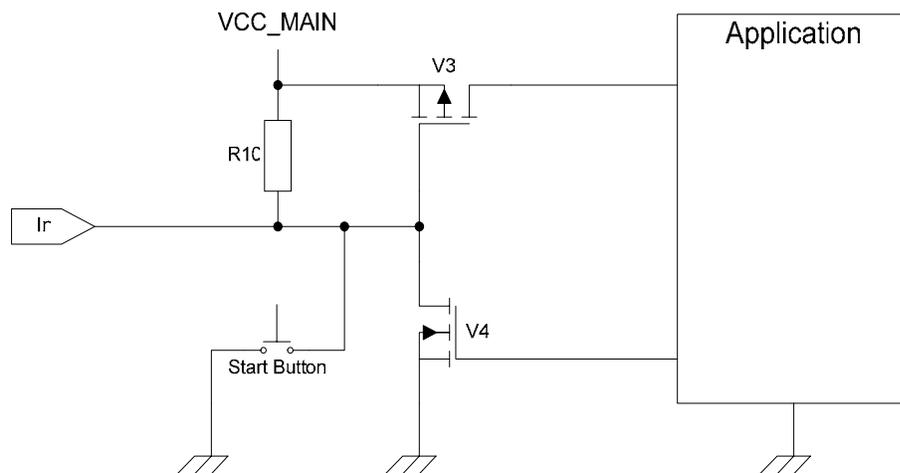


Figure 5.20-3 Example of host wake-up circuit

5.21 Ringer Output (BUZZER) [to be implemented in a future release]

Pin	Name	Direction	Function
52	BUZZER	Output	Buzzer output

Connecting the BUZZER signal to an inverting transistor-buffer followed by a piezoelectric transducer enables the wireless modem to play pre-programmed melodies or sounds.

6 Antenna Connector

The wireless modem's antenna connector allows transmission of the radio frequency (RF) signals from the wireless modem to an external customer supplied antenna. The connector is a micro-miniature coaxial WFL surface mounted component. Suitable WFL type mating plug are available from the following manufacturers;

- Hirose

The nominal impedance of the antenna interface is 50 ohms.

Feature	GSM850	E-GSM900	GSM1800	GSM1900
Frequency range (MHz)	824-894	880-960	1710-1880	1850-1990
Maximum power	33dBm(2W)	33dBm(2W)	30dBm(1W)	30dBm(1W)
Antenna Connector impedance	50 ohms			
Antenna VSWR	2.5:1 max			

7 Hints for Integrating the Wireless Modem

This chapter gives you advice and helpful hints on how to integrate the wireless modem into your application from a hardware perspective.

Please read and consider the information under the following headings before starting your integration work:

- Safety advice and precautions.
- Installation of the wireless modem.
- Antenna.

7.1 Safety Advice and Precautions

7.1.1 General

- Always ensure that use of the wireless modem is permitted. The radio device may present a hazard if used in proximity to personal medical electronic devices. As a rule, the wireless modem must not be used in hospitals or onboard aircraft.
- You are responsible for observing your country's safety standards, and where applicable the relevant wiring rules.
- Never use the wireless modem at a gas station, refueling point, blasting area or in any other environment where combustible vapors or explosives may be present.
- Operating the wireless modem close to other electronic devices, such as antennas, television sets, and radios may cause electromagnetic interference.
- Never try to dismantle the wireless modem yourself. There are no components inside the wireless modem that can be serviced by the user. If you attempt to dismantle the wireless modem, you may invalidate the warranty.
- To protect the power supply cables and meet the fire safety requirements, it is recommended that the electrical circuits are supplied with a power regulator. The power regulator should be placed as close to the terminals of the power supply as possible.

- Do not connect any incompatible component or product to the module.



Sony Ericsson does not warrant against defects, malfunction, non-conformities or deviation caused by the connection of incompatible components or products to the GS64.

- The connection/disconnection method for the development board is by means of the DC power jack. For this reason, the mains supply should be situated close to the development board and be easily accessible.

7.2 SIM Card

- Before handling any SIM card, users should ensure that they are not charged with static electricity. Use proper precautions to avoid electrostatic discharges. The wireless modem must be switched off before the SIM card is installed or uninstalled.
- When the SIM card holder is opened, the SIM card connections lie exposed under the SIM card holder. CAUTION: Do not touch these connections! Failure to heed this advice may release an electrical discharge that could damage the wireless modem or the SIM card.
- When designing applications, the SIM card's accessibility should be taken into account. Sony Ericsson recommends that users protect SIM card access by a PIN code. This will ensure that the SIM card cannot be used by an unauthorized person.

7.3 Antenna

- If the antenna is to be mounted outside, consider the risk of lightning.
- Always follow the instructions provided by the antenna manufacturer.
- Never connect more than one wireless modem to a single antenna.
- The wireless modem can be damaged by radio frequency energy from the transmitter of another adjacent wireless transmitter.

- Like any mobile station, the antenna of the wireless modem emits radio frequency energy. To avoid EMI (electromagnetic interference), users must determine whether the application itself, or equipment in the application's proximity, requires further protection against radio emission and the disturbances it might cause. Protection is secured either by shielding the surrounding electronics or by moving the antenna away from the electronics and the external signals cable.
- The wireless modem and antenna may be damaged if either come into contact with ground potentials other than the one in the users application. Beware, ground potential are not always what they appear to be.
- In the final application, the antenna must be positioned more than 20 cm away from human bodies. When this rule cannot be applied, the application designer is responsible for providing the SAR measurement test report and declaration.
- Even if SAR measurements are not required, it is considered good practice to insert a warning in any manual produced, indicating it is a radio product and that care should be taken.

7.4 Installation of the Wireless modem

7.4.1 Where to Install the Wireless modem

There are several conditions which need to be taken into consideration when designing your application as they might affect the wireless modem and its function. They are:

7.4.1.1 Environmental Conditions

The wireless modem must be installed so that the environmental conditions stated in the Technical Data chapter, such as temperature, humidity and vibration are satisfied. Additionally, the electrical specifications in the Technical Data section must not be exceeded.

7.4.1.2 Signal Strength

- The wireless modem has to be placed in a way that ensures sufficient signal strength. To improve signal strength, the antenna can be moved to another position. Signal strength may depend on how close the wireless modem is to a radio base station. You must ensure that the location at which you intend to use the wireless modem, is within the network coverage area.

- Degradation in signal strength can be the result of a disturbance from another source, for example an electronic device in the immediate vicinity. More information about possible communication disturbances can be found in section 8.3.5, page 59.
- When an application is completed, you can verify signal strength by issuing the AT command AT+CSQ or AT+E2EMM. See the AT Commands Manual for further details.



Before installing the wireless modem, use an ordinary mobile telephone to check a possible location for it. In determining the location for the radio device and antenna, you should consider signal strength as well as cable length.

7.4.1.3 Connection of Components to Wireless modem

- The integrator is responsible for the final integrated system. Incorrectly designed or installed, external components may cause radiation limits to be exceeded. For instance, improperly made connections or improperly installed antennas can disturb the network and lead to malfunctions in the wireless modem or equipment.

7.4.1.4 Network and Subscription

- Before the integrator's application is used, the user must ensure that their chosen network provides the necessary telecommunication services. Integrators should contact their service provider to obtain the necessary information.
- Integrators intending to use SMS in the application should ensure this is included in their (voice) subscription.
- Similarly, integrators intending to use GPRS for data services should also ensure that this service is available on their network and in their account plan.
- Users should consider the choice of the supplementary services described in section 2.3.2 Short Message Service, page 14.

7.4.2 How to Install the Wireless modem

7.4.2.1 Power Supply

Use a high-quality power supply cable with low resistance. This ensures that the voltages at the connector pins are within the allowed range, even during the maximum peak current. An electrolytic capacitor should be placed close to the power supply pins of the wireless modem to supply the peak currents during burst transmission. See 5.5 Regulated Power Supply Input (VCC), page 34.

7.4.2.2 Grounds

A ground connection is provided at the mounting hole next to the RF connector on the wireless modem (see Figure 5.1, page 19). Connect this ground point to the GND pins of the wireless modem by the shortest, low impedance path possible. The purpose of this connection is to allow any ESD picked up by the antenna to bypass the wireless modem's internal ground path.

Note! It is recommended that you use a cable with a maximum resistance of 5 milliohm for the ground connection.

Note! AREF and GND are connected at a single point inside the wireless modem. They must not be joined together in your application.

7.4.2.3 Audio

Use a coupling capacitor in AUXI line if the application does not use the wireless modem's bias voltage. See also Figure 5.9-1 Microphone connections to the wireless modem, page 50.

7.4.2.4 Software Upgrade

There are two ways of updating the firmware in the GS64. There is a web based tool that can access a Sony Ericsson server from where SW can be downloaded. There is also an Updater, which is a local application that downloads an image provided by SEMC.

7.5 Antenna

7.5.1 General

The antenna is the component in the users system that maintains the radio link between the network and the wireless modem. Since the antenna transmits and receives electromagnetic energy, its efficient function will depend on:

- the type of antenna (for example, circular or directional)
- the placement of the antenna
- communication disturbances in the vicinity in which the antenna operates

In the sections below, issues concerning antenna type, antenna placement, antenna cable, and possible communication disturbances are addressed.

In any event, users should contact their local antenna manufacturer for additional information concerning antenna type, cables, connectors, antenna placement, and the surrounding area. Users should also determine whether the antenna needs to be grounded or not. Usually, a local antenna manufacturer should be able to design a special antenna suitable for the integrators application and environment.

7.5.2 Antenna Type

Users should ensure that they choose the right type of antenna for the wireless modem.

The antenna must be designed for the frequency bands deployed in the regions that the wireless modem is being used. For fixed locations this may be dual bands (for example E-GSM900/GSM1800 in Europe; GSM850/GSM1900 in North America). For applications which are mobile, users should consider whether three or all four GSM bands could be encountered.

Other factors in choosing antenna are equally important:

- the impedance of the antenna and antenna cable must be 50 ohms at all frequencies being used
- the antenna output-power handling capability must be a minimum of 2 W
- the antenna VSWR value should be less than 3:1 to avoid damage to the radio device

7.5.3 Antenna Placement

The antenna should be placed away from electronic devices or other antennas. The recommended minimum distance between adjacent antennas, operating in a similar radio frequency band, is at least 50 cm.

If signal strength is weak, it is useful to face a directional antenna at the closest radio base station. This can increase the strength of the signal received by the wireless modem.

The wireless modem's peak output power can reach 2 W. RF field strength varies with antenna type and distance. At 10 cm from the antenna the field strength may be up to 70 V/m and at 1 m it will have reduced to 7 V/m.

In general, CE-marked products for residential and commercial areas, and light industry can withstand a minimum of 3 V/m.

7.5.4 The Antenna Cable

Use 50 ohm impedance low-loss cable and high-quality 50 ohm impedance connectors (frequency range up to at least 2 GHz) to avoid RF losses. Ensure that the antenna cable is as short as possible.

The effectiveness of the antenna, cable and connectors is determined by their quality. All connectors, adaptors and cables should be of the highest quality, lowest loss, lowest VSWR rating that is affordable to the user.

Minimize the use of extension cables, connectors and adapters. Each additional cable, connector or adapter will result in additional loss of signal power.

7.5.5 Possible Communication Disturbances

Communication disturbances can adversely effect the quality of wireless links, including the following causes:

- Noise can be caused by electronic devices and radio transmitters.
- Path-loss occurs as the strength of the received signal steadily decreases in proportion to the distance from the transmitter.
- Shadowing is a form of environmental attenuation of radio signals caused by hills, buildings, trees or even vehicles. This can be a particular problem inside buildings, especially if the walls are thick and reinforced.

- Multi-path fading is a sudden decrease or increase in the signal strength. This is the result of interference caused when direct and reflected signals reach the antenna simultaneously. Surfaces such as buildings, streets, vehicles, etc., can reflect signals.

8 Embedded Applications

The wireless modem has the capability to store and run customer written code in the form of a script during the processor's idle time, through the use of an on board interpreter.

8.1 Features

Main features of embedded applications are as follows:

- C based scripting language (Sony Ericsson specific)
- Over the air upgrade of scripts (NOT GSM software)
- Library of intrinsic functions
- 2 scripts can be stored in the memory at any time (but only 1 can be active)

8.2 Implementation

The wireless modem has up to 256k of space available for storage of two scripts in the scripting language and TBD of operating RAM. Structures included in this language are:

- If - then - else statements
- While loops
- For loops

All hardware interfaces that are normally available to the wireless modem through the AT commands are available to the embedded application.

Further drivers have been written such as M bus, keypad, SPI and I2C for use by the embedded application (EA) through the use of the I/O pins.

8.2.1 Limitations

Since the wireless modem is processing the script using its own memory, limitations are placed onto the scripts that are run.

- A direct comparison cannot be made to a fully compiled C program in terms of size, but a gauge of script size is that if each line were 128 characters long in the script then the script could be about 16,000 lines long.

- Processing power is something that needs to be considered as the script is run as a low priority process within the software. However, controller mode stops GSM operation and provides all the processing power for the script to be run. See the *M2mpower Application Guide* for more details.
- Code cannot be ported directly from an existing application and loaded directly onto the wireless modem. It must be re-written in the Sony Ericsson Mobile script language so that the wireless modem interpreter can function correctly.

8.2.2 M2mpower IDE (Integrated Development Environment)

The IDE is a Windows based package which allows the user to write, simulate, debug and download the application into a wireless modem with the embedded application (EA) software. The standard version is designed to run on Windows XP and 2000.

The M2mpower Application Guide is available for implementing applications using the developer's kit and the embedded application (EA) functionality.

This is a required package to be able to implement an embedded application (EA).

For further information please contact Sony Ericsson Mobile Communications customer support.

9 TCP/IP Stack

An on board IP/TCP/UDP stack has been integrated into the software negating the need for the customer to implement one in their own code base.

This is accessible by using an embedded applications (see section 9) using intrinsic functions or through AT commands.

9.1 Implementation

The following types of commands allow various functions:

- Open/closing IP connection – Negotiates/closes a dynamic IP address with the web server.
- Send/Receive TCP packets – Performs all TCP operations to send and receive packets.
- Send/Receive UDP packets – Performs all UDP operations to send and receive packets.
- Resolve URL to an IP address – Similar to nslookup command in DOS When the unit is set up and controlled using the embedded applications

10 Technical Data

10.1 Mechanical Specifications

Refer to Figure 4.2-1 Dimensions of the Wireless modem for reference to mechanical features.

Mechanical Feature	Variant	Value
Length		37 mm
Width		30 mm
Thickness (see illustration below)	without SIM holder	2.67 mm
	with SIM holder	5.27 mm
Weight		

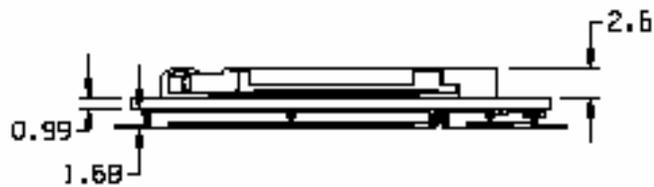


Figure 10.1-1 GS64 module with thickness dimensions

10.2 Power supply voltage, normal operation

Parameter	Mode	Limit
VCC Supply voltage	Nominal	3.6 V
	Min	3.2 V
	Max	4.5 V
	Absolute maximum limit	-0.3V to 6.5V
	Maximum supply ripple	<100mV @<200kHz <20mV @>200kHz
Maximum allowable voltage drop	Transmission burst	200mV
Maximum current consumed	Full power (2W) transmit	2250 mA (peak)
		2100 mA (avg)



WARNING

Stresses in excess of the absolute maximum limits can cause permanent damage to the device. These are absolute stress ratings only. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of the data sheet. Exposure to absolute maximum ratings for extended periods can adversely affect device reliability.

10.3 Radio specifications

Feature	GSM850	E-GSM900	GSM1800	GSM1900
Frequency range (MHz)	824–894	880–960	1710–1880	1850–1990
Maximum power	33dBm (2W)	33dBm (2W)	30dBm (1W)	30dBm (1W)
Antenna impedance	50 ohms			

10.4 SIM card

Parameter	1.8V	3.0V	5.0V
External SIM support	Yes	Yes	No
Integrated SIM support (optional)	Yes	Yes	No

10.5 Environmental Specification

Test Case	Test Summary	Ref Standard
Heat Test	Temp: max storage Humidity: nominal Duration: 16 hours	IEC 60068-2-2
Cold Test	Temp: min storage Duration: 16 hours	IEC 60068-2-1
Temperature Cycling	Temp (low) : min storage Temp (high) : max storage 2 hrs dwell at each extreme 6 hrs transition between temps Duration: 5 cycles x 16 hours (80 hrs total)	IEC 60068-2-14
Thermal Shock Test	Temp (low) : min storage Temp (high) : max storage 6 min dwell at each extreme 0.5 to 3 min transition Duration: 30 cycles (Group 2,3)	IEC 60068-2-14
Moist Heat Cyclic Test	Temp (low) : nominal ambient Temp (high) : max operating Humidity (high) : 95% ±5% RH Humidity (low) : 93% ±5% RH 9 hr dwell at each temperature 3 hr transition between temps Duration: 6 cycles x 24 hours (144 hrs total)	IEC 60068-2-30
Operational Durability	SIM insertion : 500 cycles System connector : 10,000 cycles Flips/Hinges : 1,000 cycles RF connector : 5,000	1/52 41-FEA 202 8370
Free Fall Test	1m drop height on to concrete - all sides - all faces - all corners - any extended features	IEC 60068-2-32 Test Ed

Test Case	Test Summary	Ref Standard
Sinusoidal Vibration	<p>Freq: 10–60 Hz, constant displacement $\cong \pm 0.35\text{mm}$</p> <p>Freq : 60–500 Hz, constant acceleration $\cong 5\text{ g}$</p> <p>Sweep velocity: 1 oct/min</p> <p>Sweeps: 5 per axis</p> <p>Axis: 3 axis (x, y, z) per device</p>	IEC 60068–2–6
Random Vibration	<p>Power Spectral Density:</p> <p>5 Hz 0.10 m^2/s^3</p> <p>12 Hz 2.20 m^2/s^3</p> <p>20 Hz 2.20 m^2/s^3</p> <p>200 Hz 0.04 m^2/s^3</p> <p>500 Hz 0.04 m^2/s^3</p> <p>Duration : 2 hrs each axis</p> <p>Axis : 3 axis (x, y, z) per device</p>	IEC 60068–2–34
Mechanical Shock Test	<p>Pulse shape: Half-sine</p> <p>Amplitude: 30 $\text{g} \pm 15\%$</p> <p>Duration: 6 ms</p> <p>Axis: $\pm x, \pm y, \pm z$</p> <p>No. shocks: 3 each direction (18 total)</p>	IEC 60068–2–27 Test Ea
Mixed Plug-in Connector	<p>Mechanical force :</p> <p>50 N in $\pm x, -y, \pm z$ directions</p> <p>100 N in $+y$ (mating axis)</p>	1/152 41-FEA 202 8370

11 Regulatory Notices



The GS64 described in this manual conforms to the Radio and Telecommunications Terminal Equipment (R&TTE) directive 99/5/EC with requirements covering EMC directive 89/336/EEC and Low Voltage directive 73/23/EEC. The product fulfils the requirements according to 3GPP TS 51.010-1, EN 301 489-7 and EN60950.

This device complies with Part 15 of the FCC rules. Operation is subject to the following two conditions:

- (1) This device may not cause harmful interference, and
- (2) The device must accept any interference received, including interference that may cause undesired operation.

FCC ID PY7BC051022

This product has not yet received GCF or FCC approval

IC: 4170B-BC051022

Append Declaration

Developers Kit

12 Introduction to the Universal Developer's Kit

The Sony Ericsson M2M universal developer's kit (UDK) is designed to get you started quickly. It contains all the hardware you will need to begin the development of an application.

The only items you need to provide are; a wireless modem, a computer, a SIM card with a network subscription, and a knowledge of programming with AT commands.

The main hardware of the UDK is an open board onto which you plug the wireless modem, using an adaptor board where necessary. Connectors, switches, jumpers and SIM card holder are provided to allow you to configure and access all the functions of the radio device.

Two version of the UDK exists; the first-generation UDK is designed for legacy M2M products available during 2003 to 2005; a second-generation Universal Developers Kit Mk 2 is available for M2M products from 2006 onwards. Components, adaptor boards and peripheral interfaces are not inter-changeable between the two UDK products.

A separate user manual describes the set-up and use of the UDK. This can be downloaded from the Sony Ericsson M2M Extranet web pages or obtained from your local sales support representative upon request.